

# Degradation of Fan Performance in Cooling Electronics: Experimental Investigation and Evaluating Numerical Techniques

Yaman. M. Manaserh<sup>1</sup>, Mohammad. I. Tradat<sup>1</sup>, Cong Hiep Hoang<sup>1</sup>, Bahgat G. Sammakia<sup>1</sup>, Alfonso Ortega<sup>2</sup>, Kouros Nemat<sup>3</sup>, Mark J. Seymour<sup>3</sup>

<sup>1</sup>Departments of Mechanical Engineering, ES2 Center, Binghamton University-SUNY, NY, USA

<sup>2</sup>Departments of Mechanical Engineering, ES2 Center, Villanova University, PE, USA

<sup>3</sup>Future Facilities, London, UK and NY, USA

E-mail: yyaseen1@binghamton.edu

## Abstract

This study reports on the essential forced air-cooled electronics issue of fan performance deterioration caused by the presence of obstructions inside Information Technology Equipment (ITE). Fan performance was characterized based on the fan's static pressure and flowrate. Three different experimental techniques (flow test chamber, pressure probe, and pressure taps) were used to measure the fan static pressure at different locations. Moreover, Computational Fluid Dynamics (CFD) models were built considering different fan working environments. Multi Reference Frame (MRF) and Lumped Fan (LF) model CFD techniques were employed. The experimental results were used to evaluate the modeling techniques whilst implemented in different working environments and to better understand how fans react to blockages inside ITE. Experiments showed that compared to the Free Environment (FE) readings, placing the fan inside a specific ITE reduced the flowrate delivered by the fan by 57.2% and decreased static pressure by 76.3%, which affects the thermal performance of the ITE cooling system. Moreover, comparing numerical results with the experimental ones showed that the MRF approach predicted the flowrate delivered by the fan with a relative error of 3.9%, while the LF approach overestimated the flowrate by 70.3%. The results and conclusions reported in this work can be expanded to cover many other applications in which fans are operating inside enclosed environments and surrounded by many obstructions.

**Keywords:** thermal management; electronics cooling; IT-equipment; axial flow fans; CFD; multiple reference frame.

## 1. Introduction

Enhancement of thermal management is becoming a bottleneck challenge that restricts the further development of many sectors such as the lithium-ion batteries industry [1-3] and the electronics industry [4-9]. Developing technology trends and increasing demand for online services have prompted rapid growth in data management, storing, and processing, which in turn has increased the waste heat dissipated by ITE [10]. These facts have prompted researchers to investigate potential solutions and reliability concerns regarding electronics thermal management. A. Taheri et al. [11] proposed a new design of a liquid-cooled heat sink to enhance the thermal performance of available cooling modules in the electronics market. B. Kanargi et al. [12] performed a numerical and experimental investigation on an air-cooled oblique- finned heat sink considering two oblique angles which are 30° and 45°. H. Saber et al. [13] performed a performance optimization study to minimize the non-uniformity of the temperature distribution in the computer chip and its power requirements. This was done by considering cascaded and non-cascaded thermoelectric devices for cooling computer chips. T. Yeom et al. [14] investigated the enhancement of parallel channels air-cooled heat sink using a piezoelectric synthetic jet array for electronics cooling. M. Yang et al. [15] conducted an- experimental study on single-phase hybrid microchannel liquid-cooled chips. Their study introduces a novel hybrid microchannel heat sink combining manifold with secondary oblique channels. These studies mainly focused on the heat sink design whether it was air cooled or liquid cooled-

Nomenclature			
CE	Chassis environment	$\bar{v}$	Average velocity ( $m s^{-1}$ )
CFD	Computational fluid Dynamics	$\vec{v}$	Absolute velocity ( $m s^{-1}$ )
$\vec{F}$	Body forces ( $kg m s^{-2}$ )	$\vec{v}_r$	Relative velocity ( $m s^{-1}$ )
FE	Free environment	$y$	Distance to the wall ( $m$ )
ITE	Information technology equipment	$y^+$	Dimensionless parameter
$k$	Turbulent kinetic energy ( $m^2 s^{-2}$ )	$\varepsilon$	Rate of turbulent kinetic energy dissipation ( $m^2 s^{-3}$ )
LF	Lumped fan	$\nu$	Kinematic viscosity
MRF	Multiple reference frame	$\rho$	Fluid density ( $kg m^{-3}$ )
$P$	Pressure ( $kg m^{-1} s^{-2}$ )	$\bar{\tau}$	Viscous stress tensor ( $kg m^{-1} s^{-2}$ )
$\dot{Q}$	Volumetric flowrate ( $m^3 s^{-1}$ )	$\vec{\omega}$	Angular velocity ( $s^{-1}$ )
SE	Server environments	<b>Subscripts</b>	
$\vec{u}$	Velocity vector ( $m s^{-1}$ )	c	Converted
$\vec{u}_r$	Whirl velocity ( $m s^{-1}$ )	w	Wall
		$\tau$	Friction

44 -heat sinks. However, heat sinks design is not the only topic that attracted the researchers' attention in the  
45 electronics cooling research field.

46 As fans continue to play an integral role in electronics cooling, researchers extensively investigated many  
47 aspects related to implementing fans in the electronics thermal management applications, such as fan  
48 geometry, fan characterization, and improving convective heat transfer. Their investigations considered  
49 different types of fans namely, axial fans [16, 17], piezoelectric fans [18, 19], and centrifugal fans [19, 20].  
50 Generally, ITEs tend to be physically dense environments. Fans often operate surrounded by multiple  
51 objects, which form obstructions that can degrade the fan's performance. Some of the obstructions' effects  
52 on fan performance have been previously studied. S.Lin and C.Chou [21] experimentally investigated the  
53 blockage effect on the performance and noise characteristics of axial-flow fans mounted on the heat sink  
54 assembly. Their results showed that the decrease in flowrate was insignificant while the static-pressure loss  
55 was dramatic. In another study [22], the authors examined the blockage effect on the radial fans and  
56 presented a comparison showing how axial and radial fans each react to blockage. They concluded that  
57 radial fans are more suitable for environments with high resistance.

58 S. Nakamura et al. [23] carried out a numerical and experimental study that discussed the influence of an  
59 upstream obstacle on the flow characteristics of axial-flow fans. It was concluded that the propagating  
60 velocity ratio depends on the non-dimensional diameter (blockage diameter to fan diameter ratio). The  
61 authors' follow-up study [24] compared the effects of upstream and downstream blockages on the fan's  
62 performance, the results of which showed that they have different consequences. At a small distance, the  
63 pressure coefficient decreased with an upstream blockage but increased with a downstream blockage. A.  
64 Al-Salaymeh and O.Badran [25] performed an experiment to identify the influence of installing various  
65 types of grilles at the fan's inlet and outlet. Their experiment showed that using some types of grilles  
66 improved fan performance. However, all of these studies experiment were performed in FE.

67 Regarding the enclosure environment, T. Fukue et al. [26] used a perforated plate to imitate ITE components  
68 in order to investigate the effect of closing part of the perforated plate on the fan performance. In another

69 work, they studied pressure drop in an enclosure with different obstructions and investigated its relationship  
70 with the  $(P-\dot{Q})$  curve. [27] Their results revealed that the intersection point of a  $(P-\dot{Q})$  curve and a flow  
71 resistance curve might not predict the actual flowrate when fans are operating inside an enclosure. In a later  
72 study, the pressure-drop around the fan in a high-density packaging ITE was evaluated by comparing the  
73 conventional pressure drop database with the experimental measurements. [28] Their evaluation aimed to  
74 predict the flowrate of a fan in ITE.

75 When it comes to cooling electronic enclosures CFD modeling, LF modeling, also known as the Abstract  
76 fan model, is the most popular approach. LF is a simplified model that calculates the flow through fans  
77 using the continuity equation and the fan performance curve, hence a pressure jump is defined between the  
78 fan inlet and outlet [29]. R. Boukhanouf and A. Haddad [30] used the LF model for conducting a numerical  
79 study on cooling electronics enclosure used in telecommunication systems. P. Nasirabadi et al. [31]  
80 performed a transient CFD analysis for thermal field long time prediction inside an electronics enclosure  
81 using the LF model. Z. Song [32] utilized the LF model in examining the fan-assisted cooling in open and  
82 closed data centers. H. Alissa et al. [33] implemented the LF model in characterizing the reliability of an  
83 open compute storage system from the server to aisle levels.

84 One of the major shortcomings for the LF approach is that it cannot predict the velocity profile of the flow  
85 leaving the fan. Instead, it assumes that the flow leaving the fan is unrealistically uniform. One proposed  
86 solution to solve the uniform flow assumption is to introduce swirl to the flow field by coupling the LF  
87 model with a model that assumes that a certain portion of the total kinetic energy (i.e. 5%) at the fan intake  
88 is responsible for generating the swirl component [34]. However, this solution is also not realistic, and it  
89 does not represent the actual fan flow field as it just transforms the uniform straight flow into a swirling  
90 flow based on assumptions made by the user. Further discussion on this matter is presented in following  
91 sections.

92 As mentioned previously, fans face the difficult issue of cooling ITE with a continuously increasing  
93 demand. Therefore, to help solve this issue, improving the accuracy with which fan cooling performance is  
94 predicted is a priority. Previous research proposed using the MRF approach as an alternative to the LF  
95 approach. [29, 34] MRF, also known as the frozen rotor model, was first presented in 1994, [35] to predict  
96 the flow fields induced by impellers in mixing vessels. The MRF approach was widely employed in  
97 characterizing fans, Y. Lee and H. Lim [36] presented a study aimed at developing an optimized design of  
98 a centrifugal blower by changing the shape of its internal components such as the external cases and the  
99 rotating fan ribs. X. Ye et al. [37] numerically investigated the effect of five blade tip patterns on the  
100 performance and acoustics of a twin-stage variable-pitch axial fan. Zhang et al. [38] examined the influence  
101 of abnormal deflection of two adjacent moving blades in an axial fan by comparing the flow field in the  
102 rotor, static and dynamic characteristics of normal blades, and four abnormal blade combinations under the  
103 rotating stall. Another study [39] performed CFD and computational aeroacoustics analyses to investigate  
104 the acoustic performance of unevenly spaced blades in a centrifugal fan with forward curved blades. The  
105 results of these studies have confirmed the reliability and the applicability of the MRF approach. Thus, it  
106 can be recognized as a potential substitution for the LF approach in modeling electronics enclosures.

107 Recently, researchers started to implement the MRF approach while modeling fans for ITE cooling  
108 applications. Studies [29] and [40] provided a validation of the MRF fan model by comparing the MRF and  
109 the LF models with the vendor flow curve for an electronic enclosure fan. The comparison of flow  
110 characteristics showed that the MRF fan model was more representative of the fan prototype than the LF  
111 model was. In the following works [41] and [34], the thermal field computed by various fan modeling  
112 techniques including MRF for air-cooled enclosures was examined. The results showed that the temperature  
113 values obtained from the LF model and the MRF technique differ considerably. Furthermore, the MRF was

114 implemented for improving the accuracy of numerical analysis of a thermal management system for a small  
115 data center [42].

116 This study aims to clarify the obstructions' effect on fan performance inside real ITE. Moreover, it focuses  
117 on assessing the accuracy of both the LF and MRF approaches in representing the fan performance inside  
118 high resistive ITEs. The fan performance was assessed based on the static pressure and flowrate. The  
119 experimental setup was designed to consider pressure measurements at different locations using three  
120 different pressure measurement techniques: pressure probe, pressure taps, and test chamber. The fan was  
121 tested experimentally in three different environments: FE, empty server Chassis Environment (CE), and the  
122 full Server Environment (SE). CFD models were developed to replicate these environments and were solved  
123 using LF and MRF approaches. The results of the two CFD approaches and the experimental results were  
124 compared. After that, the fan's flow field was investigated thoroughly at different locations within the  
125 system. What distinguishes this study is that it investigates the fan performance inside its actual working  
126 environment instead of testing it in FEs. Additionally, this work considers how fan performance is affected  
127 by actual blockages rather than disks that imitate blockages. The results of this study show that some  
128 blockages have a significant effect on fan performance, depending on the size of the blockage, distance  
129 from the fan, and the working environment. This work may also provide researchers and industry engineers  
130 with a general idea of the margin of error present when modeling fans inside high-density ITEs and the best  
131 technique to use in their models. Finally, since fans are used for cooling and ventilation purposes in many  
132 other applications that have a similar working environment to the ITEs, the conclusions of this study are  
133 not limited to electronics cooling and it can be beneficial in such applications as well for instance,  
134 automotive industry and electrical devices (power supplies, projectors, etc.).

## 135 **2. Experimental setup**

### 136 **2.1. Testing environments**

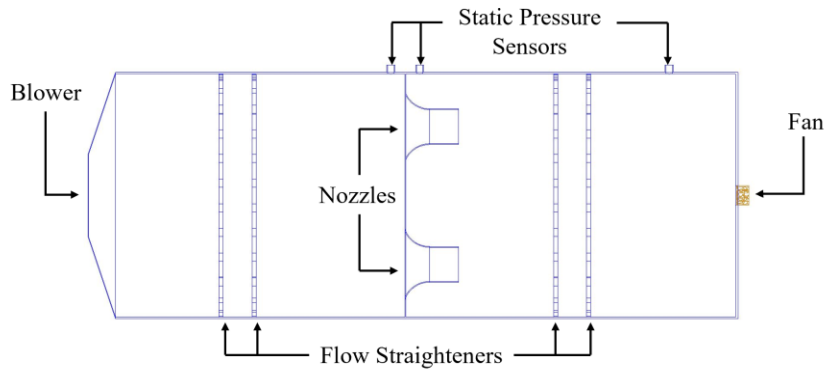
137 The fan was tested in three different environments. The reason behind this is to show how the fan reacts to  
138 different operating environments. Additionally, it can give an overall estimation of the error that could  
139 result from using the fan performance curve to predict fan performance in such environments.

140 The first testing environment, which is referred to as FE, is most similar to the environment that vendors  
141 use to conduct their fans performance curves in which the fans are tested according to a set of standards.  
142 One of the most widely adopted standards in the fan industry is "ANSI/AMCA Standard 210-16/ ASHRAE  
143 Standard 51-16: Laboratory Methods of Testing Fans for Certified Aerodynamic Performance Rating" [43].  
144 By testing the fan in this environment, a flow curve was attained which was used as a reference for fan  
145 performance when there are no blockages.

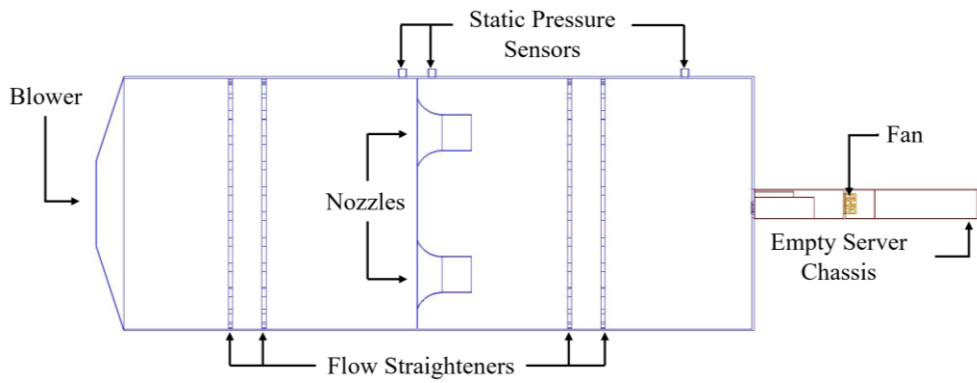
146 In the second testing environment, which is called the CE, the fan was installed inside an empty server  
147 chassis (no components) and this chassis was connected to the flow chamber. By testing the fan in this  
148 environment, the enclosure effect on the fan behavior was investigated.

149 The third testing environment, which is referred to as SE, is about testing the fan inside a server chassis  
150 containing all of the chassis components as blockages. By testing the fan in this environment, the  
151 researchers aim to clarify how the fan performs inside actual ITE and obtain a general idea of fan  
152 performance degradation inside actual ITE. However, given that different ITE configurations will produce  
153 different fan behaviors, the results of this study cannot be generalized to all fan-ITE configurations. The  
154 three testing environments and the 3D views of both CE and SE are shown in Fig.1.

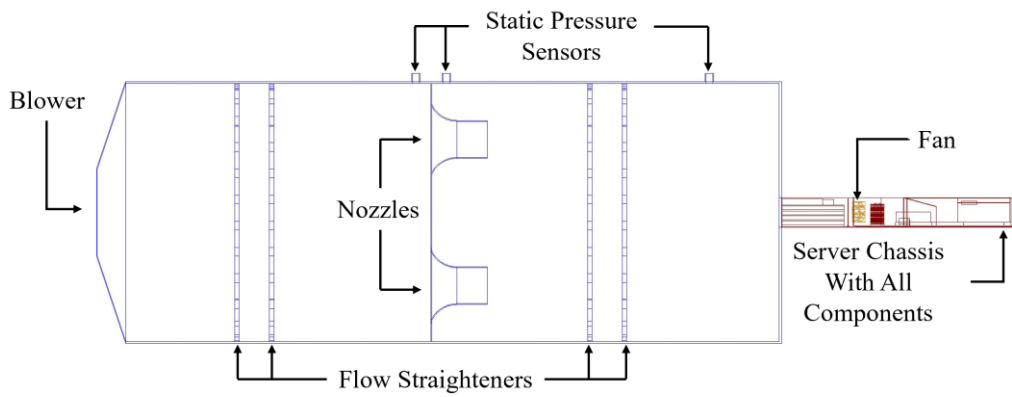
155



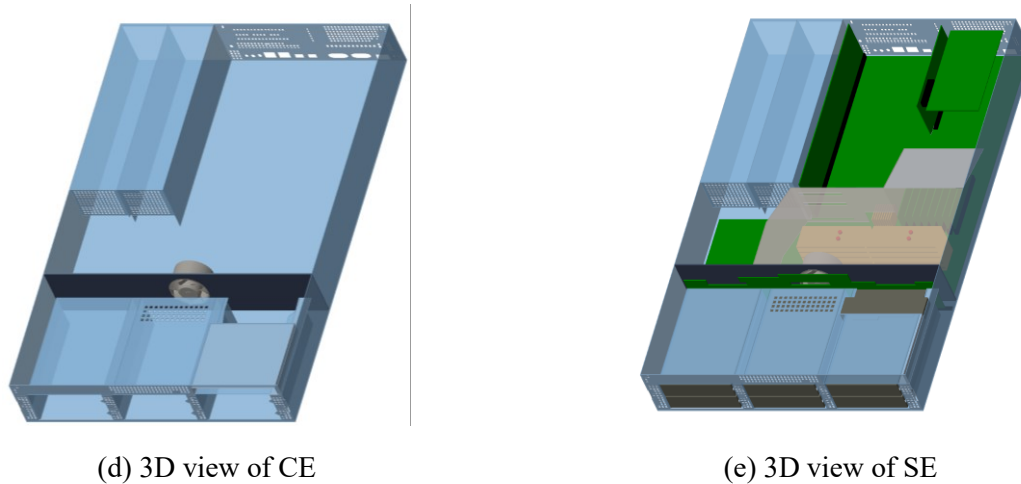
(a) FE



(b) CE



(c) SE



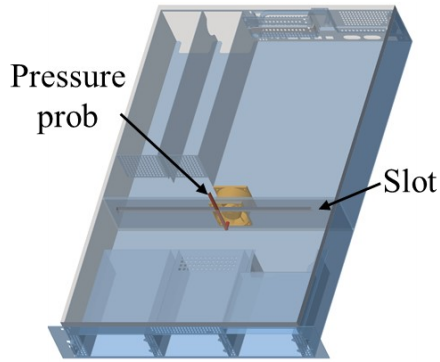
**Fig. 1.** Schematic diagram and 3D views of different working environments.

156 **2.2. Measurements techniques**

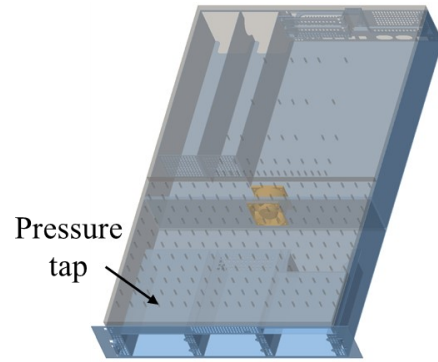
157 The fan flowrate was reported based on the differential pressure across the flow chamber nozzles.  
 158 Simultaneously, the static pressure was measured inside the chamber near the fan inlet. For both CE and  
 159 SE, the static pressure sensor measurements from the chamber did not represent the actual static pressure  
 160 generated by the fan, because they were taken far away from it (distance between fan and test chamber  
 161 sensor). Therefore, two additional methods of pressure measurement were introduced to obtain more  
 162 accurate pressure measurements.

163 The second technique was a static pressure probe, which was used to measure the static pressure inside the  
 164 server. The first step in this process was replacing the server cover with a plexiglass sheet. Next, a slot was  
 165 drilled into the sheet at the fan inlet location for a probe to be inserted through. A linear motion mechanism  
 166 was then used to drive the pressure probe along the slot to take measurements at different locations. To  
 167 avoid interrupting the flow, a small diameter probe was used, the details of which are presented in Fig. 2  
 168 (a) and (c). One drawback of this technique is that it has a space limitation, so if the ITE is spaced too  
 169 densely, then using this technique is not possible.

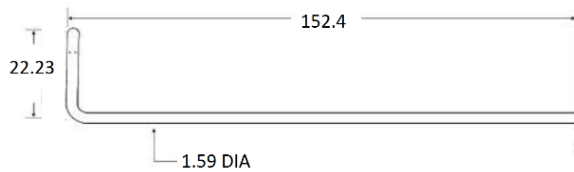
170 The third technique was pressure taps, which were used to measure the static pressure at the enclosure's  
 171 cover near the fan inlet. Pressure taps were drilled into a half-inch plexiglass sheet, which was used to  
 172 replace the cover of the enclosure. The geometry of the pressure taps was obtained from [44]. The pressure  
 173 taps hole has two diameters, one to fit the stainless steel tubulation and the other one is to take  
 174 measurements. A plastic tube was used to connect the stainless steel tubulation to the pressure transducer  
 175 to take pressure measurements through the taps. An advantage of this technique is that it is not limited by  
 176 the available space. However, its disadvantage is that it cannot provide detailed pressure measurements  
 177 from inside the enclosure. Fig. 2 (b) and (d) show the third pressure measurement technique in detail.



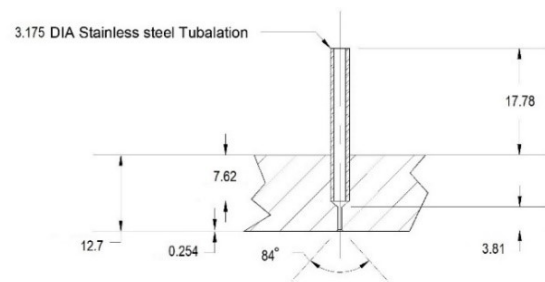
(a) Pressure probe inserted through a slot in the plexiglass cover.



(b) Pressure taps drilled into the plexiglass cover.



(c) Dimensions of the static pressure probe



(d) Details of the static pressure tap

**Fig. 2.** Static pressure measuring techniques.

178 Before running the test, it was important to obtain the time required by the fan to reach steady- state. The  
 179 fan was turned on for 15 seconds which is the time assumed to reach steady state. Then, measurements  
 180 were taken every 30 seconds for 5 minutes. The average and the standard deviation were calculated for  
 181 these pressure measurements. Thereafter, the average was compared with two readings taken at 15 and 20  
 182 minutes. In order to conduct a thorough investigation, the pressure readings were taken at different fan  
 183 flowrate. Fan flowrate was controlled using a variable openness gate. From Table 1, it can be inferred that  
 184 15 seconds is sufficient time to ensure the steady state conditions. It should be noted that these  
 185 measurements were taken in an arbitrary environment that is not discussed in this paper for the sake of  
 186 simplicity and consistency of the manuscript. This environment is similar to the CE but with some  
 187 blockages installed inside it. This explains the small difference between these measurements and the SE  
 188 ones reported in following sections. However, the time for reaching steady state is observed to be the same  
 189 for all environments.

### 190 **2.3. Instrumentation and experiment procedure**

191 In this experimental setup, a flow test chamber was utilized to control the flowrate and to measure the static  
 192 pressure near the chamber outlet. In CE and SE, the additional static pressure readings collected through  
 193 the pressure taps and the pressure probe were done using a pressure transducer and a DAQ (data acquisition)  
 194 system. For the ITE configuration in SE, the pressure probes could not be used due to limited space, hence  
 195 pressure measurements were collected using the pressure taps. In addition, a DC source and a tachometer  
 196 were used to control the fan speed. The fan speed was maintained constant by adjusting the power supply  
 197 output voltage [21, 27]. In all experiments conducted in this study, the fan rotational speed was set to 12000

198 RPM, which equals to the vendor’s testing speed. This speed was adopted to keep consistency in our results  
 199 and to execute a fair comparison between our results and the vendor’s ones.

200 Even if the fan power is an essential factor for characterizing fans, the fan’s power was not recorded along  
 201 the experiment. This is attributed to the fact that this study aims to characterize the fan’s performance in  
 202 cooling electronics rather than characterizing the fan itself. However, general observation of the fan power  
 203 during the experiment revealed that the fan consumes more power in highly resistive environment (SE)  
 204 compared to the FE, although tests were conducted at an equal rotational speed. More in-depth discussion  
 205 on the fan power variation when it is being blocked can be found in [23, 24].

**Table 1**  
 Static pressure reading variation with time.

Time	$\dot{Q}=0$		$\dot{Q}=16 \times 10^{-3}$		$\dot{Q}=24.07 \times 10^{-3}$	
	$(m^3 \cdot s^{-1})$		$(m^3 \cdot s^{-1})$		$(m^3 \cdot s^{-1})$	
	Pressure $P$ (Pa)	Standard deviation	Pressure $P$ (Pa)	Standard deviation	Pressure $P$ (Pa)	Standard deviation
5 mins (average)	225.18	1.14	110.78	1.14	46.36	1.319
15 mins	225.95	-	110.73	-	45.79	-
20 mins	225.45	-	111.23	-	46.28	-

206

207 To yield reliable measurements while characterizing the fan performance, all experimental work was  
 208 conducted using a test chamber that was designed in accordance with AMCA 210-99 standards [45]. An  
 209 appropriate size nozzle was installed in the chamber to capture the whole fan performance curve. Moreover,  
 210 a non-contact tachometer (Uni-t ut372) was used to avoid interfering with the fan performance. The merit  
 211 of this tachometer is that it has a high accuracy (0.04%  $\pm$ 2dgt) over a considerably wide measurements  
 212 range (0~99999 RPM).

213 Besides the test chamber pressure sensor, a pressure transducer with relatively low differential pressure  
 214 measurement range (1333 Pa) was used to take measurements through the pressure taps and the pressure  
 215 probe, it was chosen to consider that the static pressure for a typical fan used electronics cooling is small.  
 216 This pressure transducer and the chamber pressure sensors were calibrated prior to running the experiments.  
 217 This was done by comparing their measurements against a variable-pressure reference device. Hence, by  
 218 changing the reference device pressure and collecting the data from our sensors, a correlation between the  
 219 actual pressure and the sensor measurement was derived which were used to improve the sensors  
 220 measurements accuracy. Instrumentation models and specifications are summarized in Table 2.

221 The experiment in the three environments was conducted according to airflow test chamber manual which  
 222 is derived from AMCA’s fan testing standards [45], the experimental procedure can be summarized as  
 223 follows (The reader is referred to Fig. 1 in locating the corresponding components when describing the  
 224 experiment procedure): in the FE, the pressure sensors were calibrated to measure zero pressure differential  
 225 with respect to the room. Next, the fan was directly connected to the flow test chamber, and the fan speed  
 226 was set to equal to the vendor’s testing speed. After that, the fan performance curve was derived by varying  
 227 the fan flow rate between zero and the free delivery point while recording the fan’s static pressure readings.  
 228 The air was initially blocked from entering the fan by the test chamber gate to record the highest pressure  
 229 that can be generated by the fan, then the gate was opened gradually, and an external blower was used to



230 control the flow rate to take deferent measurements until the free delivery point is achieved, at which the  
 231 static pressure at the fan inlet equals to zero. Next, the flowrate at different points was reported using the  
 232 pressure difference across the nozzle and the vendor’s pressure differential- flowrate charts for the used  
 233 specific nozzle. Finally, these different flow delivery readings were used along with corresponding static  
 234 pressure measurements to plot the fan performance curve. Regarding the CE and the SE, a similar procedure  
 235 was followed except that the fan is installed in a different environment while pressure measurements are  
 236 simultaneously recorded through the flow test chamber sensor and the pressure probe or the pressure taps.  
 237 Also, in these two environments, the flow is restricted to pass around the fan by installing an obstruction as  
 238 shown in Fig.1 (d) and (e).

**Table 2**

Details of instrumentation used in the experimental setup.

Instrument	Specifications
Airflow test chamber	Designed in accordance with AMCA 210-99 standards.
DC source	KEYSIGHT E3634A
Tachometer	Uni-t ut372 (accuracy : 0.04% ±2dgt)
Pressure transducer	MKS 698A (accuracy: 0.08% of the reading)
DAQ	National Instruments cDAQ-9171

239

### 240 **3. Numerical modeling**

#### 241 **3.1. Simulation method**

242 Simulations were carried out using the commercial CFD package of Fluent. The following assumptions  
 243 were made while running the simulations: heat transfer between solid bodies and the air is negligible, air is  
 244 incompressible and has constant properties, and the impacts of wall roughness and gravity are negligible.  
 245 Based on these assumptions, the energy equation was disregarded. The boundary conditions of the inlet and  
 246 outlet were set as pressure-based conditions. The value of the inlet pressure boundary was adjusted to  
 247 measure the different points of the fan performance ( $P-\dot{Q}$ ) curve while keeping constant zero pressure at  
 248 the outlet.

249 Two CFD approaches were deployed to model the fan in different environments. The first approach is the  
 250 LF model. Due to the simplicity of this model and the fact that it is computationally inexpensive, it is the  
 251 most widely adopted fan modeling approach in the electronics cooling industry. In this approach, fan  
 252 geometry is replaced by a 3D solid body or a 2D surface replicating the fan dimensions. Between the fan’s  
 253 upstream and the downstream faces, the fan flowrate is calculated using the continuity equation and a  
 254 pressure jump function without solving the Navier-Stokes equations. The pressure jump function is  
 255 typically derived from the vendor’s fan performance curve. In this study, the pressure-rise ( $\Delta P$ ) across the  
 256 fan was specified as a function of average-velocity ( $\bar{v}$ ) normal to the fan. The average velocity through the  
 257 fan was calculated by utilizing the vendor fan performance ( $P-\dot{Q}$ ) curve as illustrated in Table 3. However,  
 258 some CFD packages are more robust as the fan performance curve is directly imported to the code, and it  
 259 will automatically generate the pressure jump function and define it for the fan.

260 According to the definition of LF approach, the flow leaving the fan is defined to be uniformly distributed  
 261 and normal to the downstream fan face. The swirl function, which is used to transform the straight flow  
 262 into swirling flow, can be incorporated into the solution in many ways such as defining Swirl Number or  
 263 Peak Impeller Efficiency, depending on the CFD package. Basically, all of these methods of defining the  
 264 swirl function are generating the swirl by imposing unrealistic tangential and radial velocity fields on the  
 265 downstream fan surface. Thus, they are all expected to fail in predicting the actual fan flow field which  
 266 results from the interaction between air and the fan components (blades, outlet guide vanes, etc.).

267 On the way how the LF approach deals with the different fan speeds, the LF model utilizes the fan affinity  
 268 laws [46] to calculate the fan flowrate  $\frac{Q_1}{Q_2} = \frac{\omega_1}{\omega_2}$ , and static pressure  $\frac{P_1}{P_2} = \left(\frac{\omega_1}{\omega_2}\right)^3$  from the fan performance  
 269 curves. Thus, if the fan is speed is different from the vendor's rated speed (the speed adopted by the vendor  
 270 while conducting their fan performance curve), the fan performance curve will be automatically modified  
 271 according to the fan affinity laws.

**Table 3**

Vendor's fan performance ( $P-\dot{Q}$ ) curve and average velocity through the fan.

Pressure $P$ (Pa)	Flowrate $\dot{Q}$ ( $m^3 \cdot s^{-1} \times 10^{-3}$ )	Average velocity $\bar{v}$ ( $m \cdot s^{-1}$ )
530.03	0	0
403.12	6.04	3.8
261.28	14.11	8.88
248.84	15	9.44
241.37	15.88	9.99
233.91	17.03	10.71
231.42	18	11.32
228.93	19.06	11.99
226.94	20.11	12.65
221.47	21.17	13.32
214	22.23	13.99
201.56	23.56	14.82
171.7	25.41	15.99
129.4	27.72	17.44
57.23	30.73	19.33
0	32.86	20.67

272

273 Based on the vendor flow curve and the corresponding average velocity through the fan, a polynomial  
 274 regression was performed to derive the fan's pressure rise function. The fifth-order polynomial that  
 275 describes the pressure jump across the fan based on the average velocity is given by Eq. 4. The goodness  
 276 of fit of the regression was tested by calculating the R-squared which was found to be equal to 99.96%.

$$\Delta P = 0.0017\bar{v}^5 - 0.0966\bar{v}^4 + 1.8465\bar{v}^3 - 12.679\bar{v}^2 - 6.7324\bar{v} + 529.92 \quad (1)$$

277 The second approach was the MRF approach, the steady state MRF approach is used to model rotating parts  
 278 in CFD using its 3D geometry. Since that the MRF approach is a steady state method, it requires  
 279 significantly lower amount of computational resources compared with the other 3D fan modeling

280 approaches that include the rotor geometry such as sliding mesh [47]. However, compared with the LF  
 281 model, the special grid treatment that needs to be done on the fan body in the MRF approach makes it more  
 282 computationally expensive than the LF approach. A detailed comparison between the number of grids  
 283 required by each approach to assure convergence is presented in a later section.

284 The MRF is modeling rotating parts by separating the fluid domain in the CFD model into rotating regions  
 285 and non-rotating regions. In the rotating region, the governing equations are transformed into a rotating  
 286 frame. By doing so, the centripetal and Coriolis acceleration are incorporated into the governing equation  
 287 [48].

288 Thereby, in the rotating region, the fluid is moving around fixed geometry (in our case fixed geometry is  
 289 the fan blades) instead of rotating the body through the non-rotating air. This is similar to taking a snapshot  
 290 and observing the instantaneous fluid streamlines around the rotating body in this certain position. This is  
 291 why this approach is also called the “frozen rotor model”. However, the following geometrical conditions  
 292 must be met to apply the MRF approach first, the rotating region must be axisymmetric second, the rotating  
 293 region must have an axis of rotation that is concentric with the rotating parts finally, all the rotating parts  
 294 must be bounded within the rotating region also, it is recommended that rotating region extends beyond  
 295 the rotating parts by a small distance [29].

296 As mentioned before, the MFR approach considered a coordinate system that steadily rotated with angular  
 297 velocity  $\vec{\omega}$  relative to a stationary (inertial) reference frame. The conservation of mass and momentum  
 298 equations (equations 2 and 3 respectively) of fluid flow for a steadily rotating frame considering the absolute  
 299 velocity formulation for the rotating frame can be written as follows [49]:

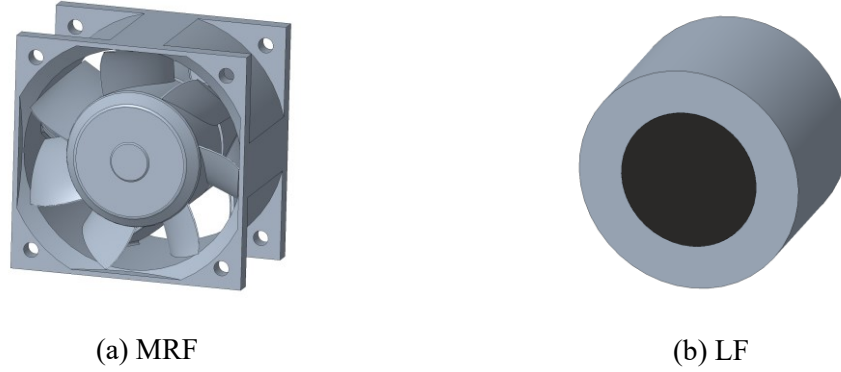
$$\nabla \cdot \vec{v}_r = 0 \quad (2)$$

$$\nabla \cdot (\vec{v}_r \vec{v}) \rho + \rho(\vec{\omega} \times \vec{v}) = -\nabla p + \nabla \cdot \vec{\tau} + \vec{F} \quad (3)$$

300 Where  $\vec{v}$  denotes the absolute velocity and  $\vec{v}_r$  represents the relative velocity,  $\vec{v}_r = \vec{v} - \vec{u}_r$ . Next,  $\vec{u}_r =$   
 301  $\vec{\omega} \times \vec{r}$  and represents the velocity due to the moving frame (whirl velocity). Then,  $\vec{\omega}$  and  $\vec{r}$  denote the  
 302 angular velocity and the position vector, respectively. Lastly,  $\vec{\tau}$ ,  $\vec{F}$  denote the viscous stress tensor and the  
 303 body forces, respectively.

304 According to these equations, the fan rotational speed in the MRF is substituted in the governing equations  
 305 to calculate the fan flow rate and static pressure in contrast to the LF approach, which substitutes the fan  
 306 speed in the fan affinity laws. Furthermore, what distinguished this approach from the LF approach is that  
 307 it considered the actual rotating body and the interaction between the rotating impeller and stationary zones.  
 308 Therefore, the MRF fan model can predict the fan’s flow fields extensively more accurately than the LF  
 309 approach. Fig. 3 shows the difference in fan shape for the LF and MRF approaches.

310 After discussing fan modeling techniques, the turbulence model needs to be introduced. The internal flow  
 311 dynamics of axial flow fans are extremely complex and different vortices are found. [50, 51] Therefore,  
 312 Reynolds Averaged Navier-Stokes (RANS) was considered. The realizable  $k$ - $\epsilon$  turbulence model was  
 313 selected to simulate the flow field through a coupling with RANS equations. This turbulence model was  
 314 selected according to the literature which has confirmed the reliability of employing the realizable  $k$ - $\epsilon$   
 315 turbulence model to solve rotating flow [52-56]. In addition, during conducting the simulation, more than  
 316 one RANS turbulence models were tested, and the results showed that the realizable  $k$ - $\epsilon$  turbulence  
 317 produced the most accurate results where some of these models did not even converge.



**Fig. 3.** Utilized fan shape in MRF and LF modeling approaches.

318

319 The realizable  $k-\varepsilon$  was coupled with the enhanced wall treatment [57], which is a near-wall modeling  
 320 method that combines a two-layer model with so-called enhanced wall functions. The exceptional  
 321 advantage of the enhanced wall treatment is that it is a  $y^+$  insensitive method. For this,  $y^+$  is a dimensionless  
 322 parameter indicating the wall coordinate,  $y^+ = \frac{y u_\tau}{\nu}$ ,  $u_\tau = \sqrt{\tau_w / \rho}$  where  $y$  is the distance to the wall,  $u_\tau$   
 323 denotes the friction velocity, and  $\tau_w$  represents the wall shear stress. Enhanced wall treatment acts as a wall  
 324 function if the first grid point is in the log-layer. Considering a near-wall mesh that is fine enough to resolve  
 325 the viscous sublayer, the enhanced wall treatment performs like the traditional two-layer zonal model.

**Table 4**  
 CFD models details

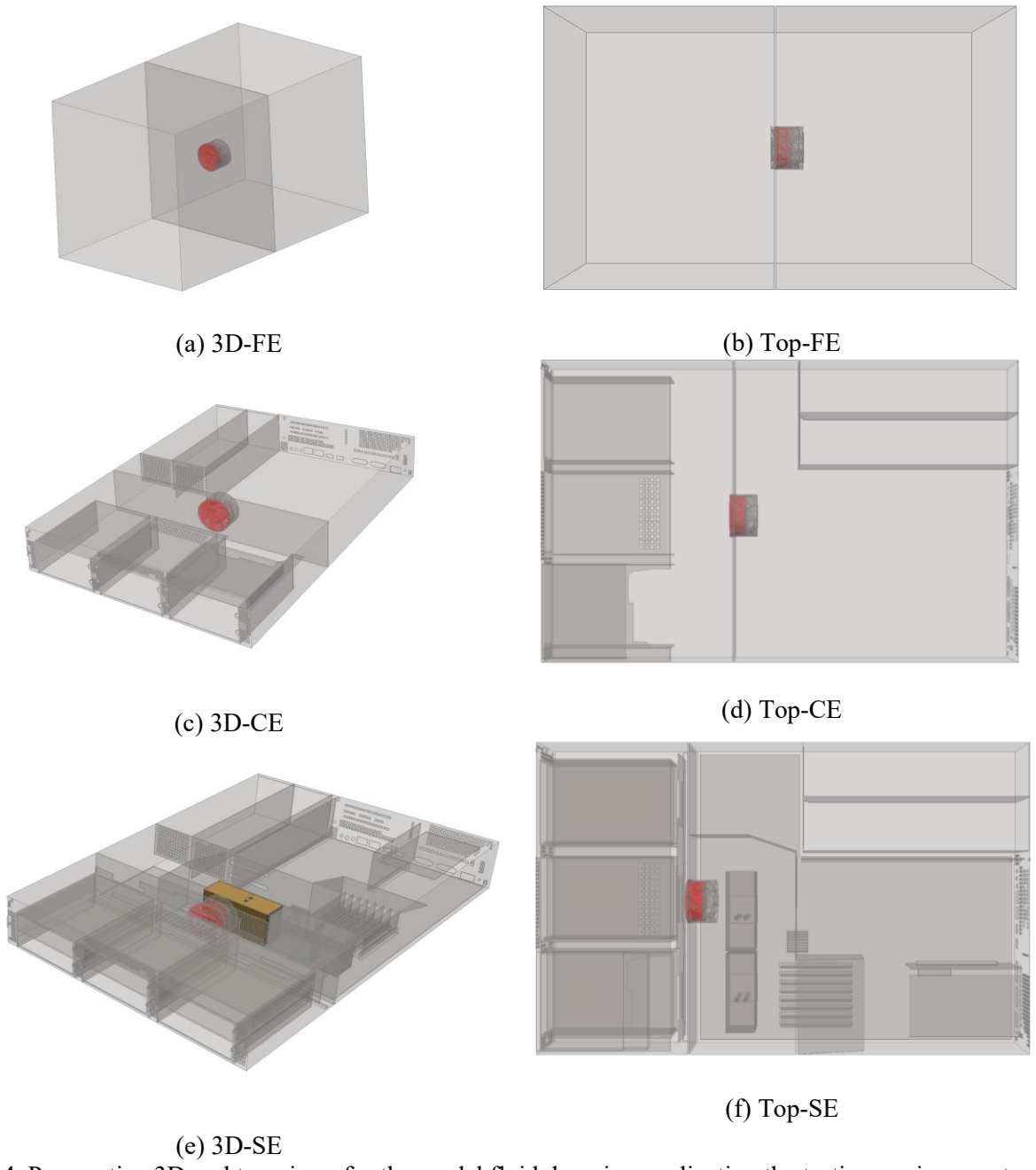
Case	Environment	CFD approach
Case 1	FE	LF
Case 2	FE	MRF
Case 3	CE	LF
Case 4	CE	MRF
Case 5	SE	LF
Case 6	SE	MRF

326

### 327 3.2. Fan model

328 CFD models were built to duplicate the three different environments. For each environment, LF and MRF  
 329 approaches were employed. Hence, a total of six models were simulated, the details of which are briefed in  
 330 Table 4. Fig. 4 introduces the 3D fluid domains that were developed based on different testing  
 331 environments. The red body represents the rotating frame. When the LF approach was used, it was replaced  
 332 by a cylindrical body as shown in Fig. 3 (b). For SE, the golden heat sink depicted in Fig. 4 (e) was used to  
 333 investigate flow distribution, which is discussed in a later section.

334



**Fig. 4.** Perspective 3D and top views for the model fluid domains, replicating the testing environments.

335 The main structure of the FE model consisted of a pressure inlet, walls upstream of the fan, and pressure  
 336 outlets downstream of it. For CE and SE, holes at the server inlet were set as pressure inlets, and chassis  
 337 walls and server components were defined as walls. Lastly, the holes at the back of the server were specified  
 338 as pressure outlets. Specific structural parameters for the environments, fan, and heat sink are shown in  
 339 Table 5.

340

341

**Table 5**

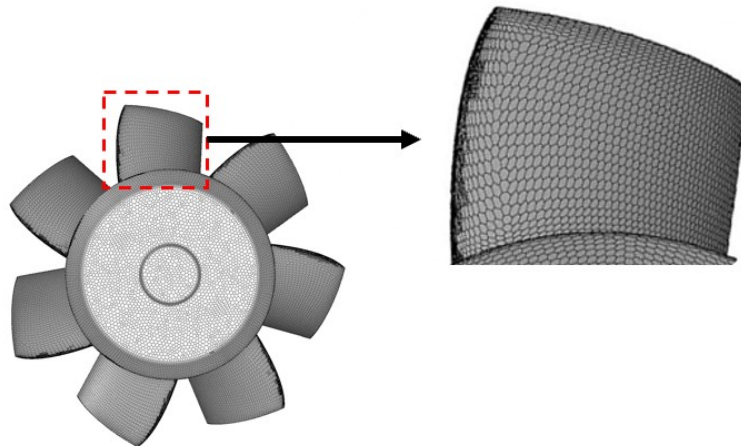
Main structural parameters.

Parameter	Value
<b>Environments</b>	
FE model dimensions ( <i>mm</i> )	(Height=360, width=360 depth=720)
Server dimensions ( <i>mm</i> )	(Height=86.4, width=444, depth=744)
<b>Fan</b>	
Fan hub diameter ( <i>mm</i> )	35
Fan inlet bell diameter ( <i>mm</i> )	64
Fan tube housing diameter( <i>mm</i> )	57
Fan rotational speed RPM	12000
Number of fan blades	7
Number of outlet guide vanes	5
<b>Heat sink</b>	
Fin dimensions	(Height=0.5, width=110 depth=40)
Number of fins ( <i>mm</i> )	30
Pitch ( <i>mm</i> )	1.88

342

343 **3.3. Grid method**

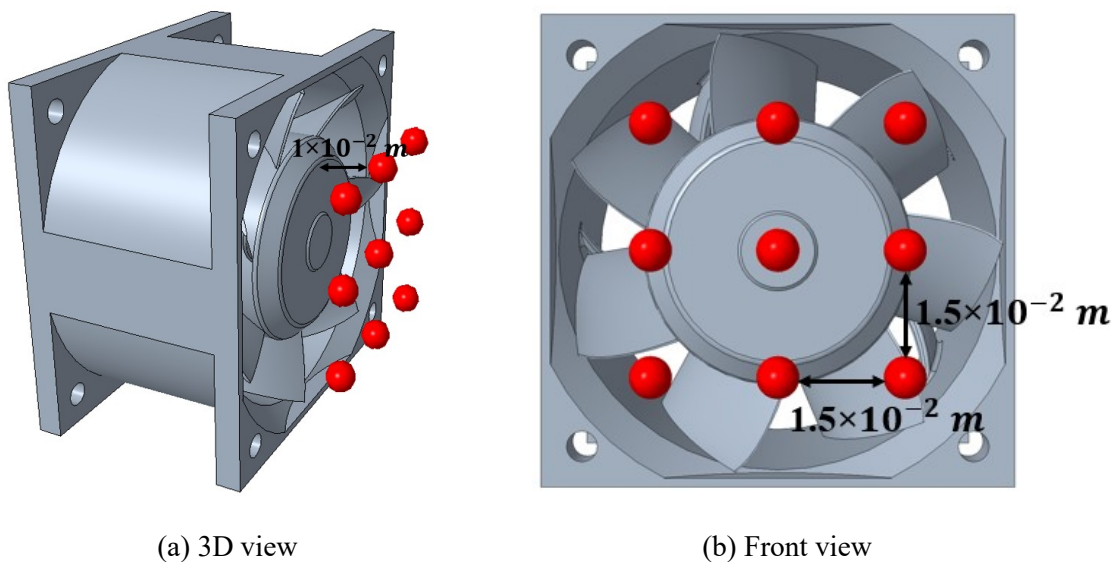
344 The computational domain was first divided into the upstream region, rotating frame or fan region, and  
345 downstream region. The grids were created using a polyhedral type element. The advantages of using  
346 polyhedral mesh were reported in [58, 59], and it has shown good performance in modeling fans [60-62].  
347 A higher number of elements was considered in the fan region. A sizing function was employed to densify  
348 the meshes at the fan walls. Contact sizing was applied at the contact surfaces between different regions to  
349 avoid sudden changes in cell size. The element growth rate was 1.1. Maximum skewness was kept under  
350 0.85, where the maximum skewness should be less than 0.97 to assure a high-quality mesh [63]. Fig. 5  
351 illustrates the grid for the fan walls.



**Fig. 5.** Mesh of the axial-fan.

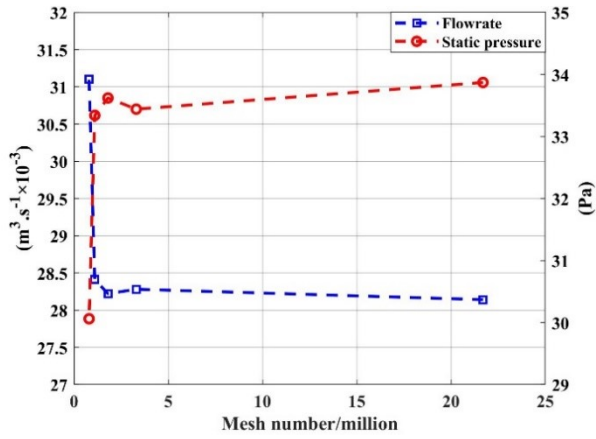
352

353 Grid sensitivity analyses were conducted to satisfy the requirements of computational accuracy and to  
 354 eliminate the effect of the grid number on the fan's flowrate and static pressure. The static pressure reading  
 355 measurement presented an average of nine pressure readings, which were taken at a  $3 \times 3$  grid  $1 \times 10^{-2} m$   
 356 away from the fan inlet as shown in Fig. 6. The grid sensitivity analyses were performed using five groups  
 357 of mesh numbers for each model mentioned in Table 4. The grid number was selected to ensure that  
 358 variation while increasing the mesh number is kept minimal. For cases 1-6, the mesh number was chosen  
 359 to be 1.5, 2.2, 1.8, 2.4, 9.4, 10.2 million, respectively. As shown in Fig. 7, MRF (case 2,4, and 6) required  
 360 a larger number of meshes for fulfilling convergence. However, the difference in terms of the grid number  
 361 between these two methods was reasonable.

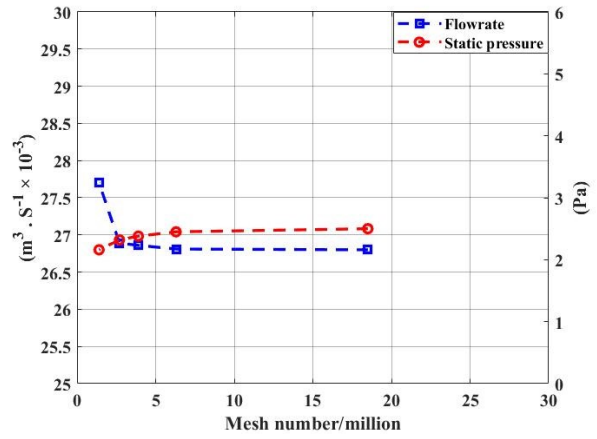


**Fig. 6.** Details of pressure measurement locations.

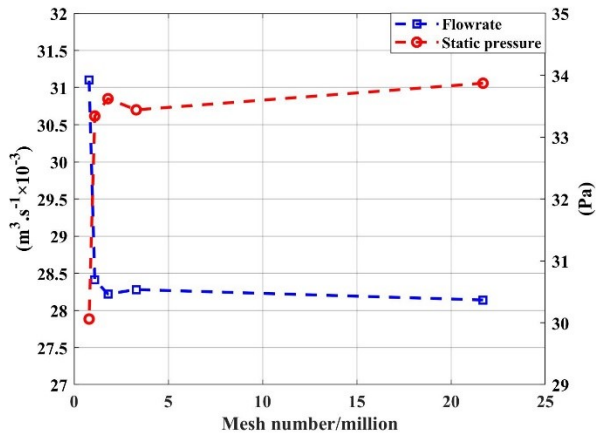
362



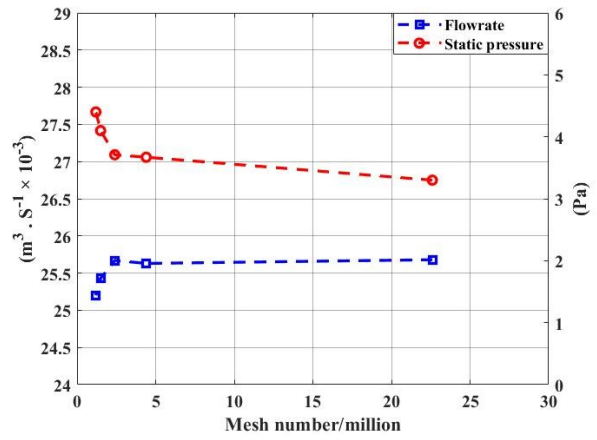
(a) Case 1



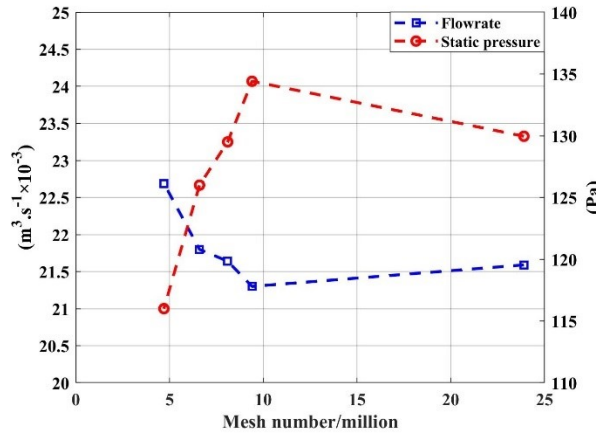
(b) Case 2



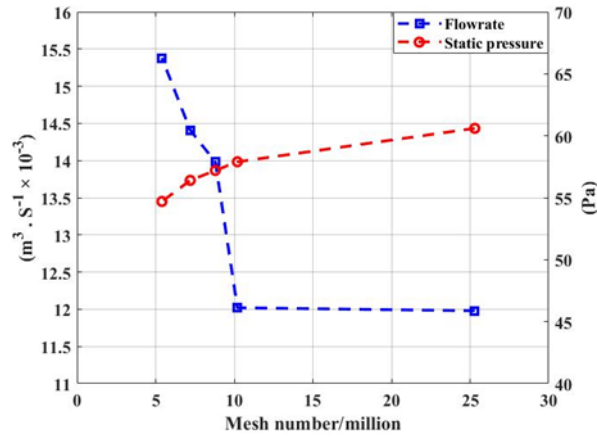
(c) Case 3



(d) Case 4



(e) Case 5



(f) Case 6

Fig. 7. Grid sensitivity analyses.

363

364



365 **4. Results and discussion**

366 **4.1. Experimental investigation**

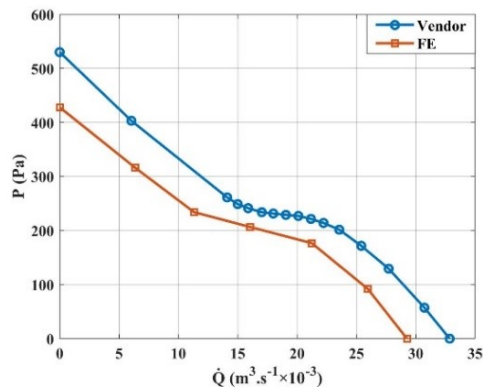
367 The first step in evaluating the effect of blockage on fan performance inside a high-density ITE is to obtain  
368 a reference for the fan performance. Using the vendor’s flow curve might introduce an error to the results  
369 because vendors generally test their fans in special flow chambers under preferable operating conditions  
370 like room temperature and humidity. This may result in an overpredicted fan performance since these  
371 conditions are not necessarily met when the fans perform in a real environment due to changing the air  
372 density.

373 Fans are constant volume machines which means that their flow flowrate is independent of air density.  
374 However, the fan’s static pressure varies proportionally with air density [64]. The variation in the fan’s  
375 static pressure due to variation in air density can be calculated using [65]:

$$P_c = P \frac{\rho_c}{\rho} \tag{4}$$

376 Where  $P_c$ ,  $\rho_c$  are the converted pressure and converted density, respectively. The fan industry rates the fan  
377 performance at a standard air inlet density, where the air density is adopted at an inlet temperature of 21°C  
378 and at a barometric pressure of 101.32 kPa [65]. In our experiment, the fan was tested at the room  
379 temperature (20-22 °C) and at the atmospheric pressure, these conditions are very similar to the fan testing  
380 standard. Thus, the difference between experimental air density and the converted one is less than 1%,  
381 which means that the experimental results reported in this work do not need to be corrected to “standard  
382 air” conditions.

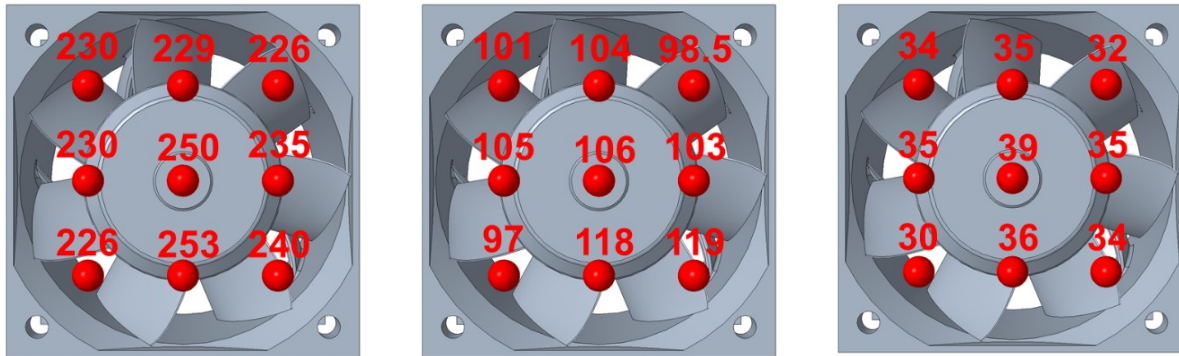
383 Another reason for the discrepancy between the experimental results and the ones reported by vendors is  
384 that fan performance can degrade with time. Hence, for the purposes of this study, a reference performance  
385 curve was obtained by testing the fan in the FE using the flow test chamber. Fig. 8 highlights the difference  
386 between the vendor flow curve and the actual flow curve. For the FE, the flow delivered by the fan was  
387 11% below what the vendor reported.



388 **Fig. 8.** Vendor’s vs actual fan performance curve.

389 After obtaining the fan performance reference curve, the next step is to investigate the effect of the server  
390 chassis on fan performance by testing the fan inside the CE. In this environment, pressure readings were  
391 collected by pressure probes, pressure taps, and the test chamber. To form a better understanding of the  
392 pressure distribution at the fan inlet, readings were taken on a 3×3 grid using a pressure probe. This is the

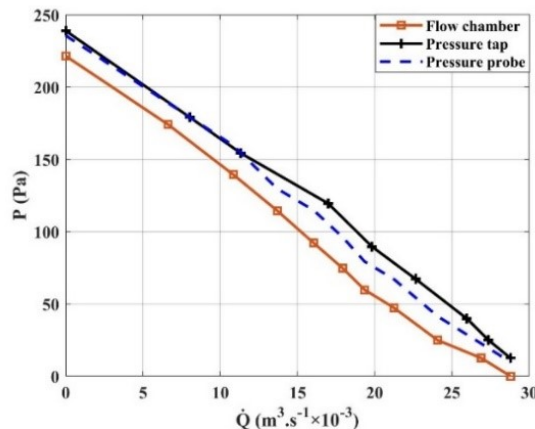
393 same method used to take measurements for the numerical models. Fig. 9 presents the pressure readings  
 394 for three different flowrates at the fan inlet.



(a)  $\dot{Q} = 0 \text{ (m}^3 \cdot \text{s}^{-1} \times 10^{-3}\text{)}$       (b)  $\dot{Q} = 16 \text{ (m}^3 \cdot \text{s}^{-1} \times 10^{-3}\text{)}$       (c)  $\dot{Q} = 24.1 \text{ (m}^3 \cdot \text{s}^{-1} \times 10^{-3}\text{)}$   
**Fig. 9.** Experimental static pressure measurement at the fan inlet in the CE.

395  
 396 Fig. 9 shows that the pressure readings vary at the fan inlet. This variation occurs due to the heterogeneous  
 397 configuration of the working environment. However, the pattern of pressure distribution changes with  
 398 different flowrates.

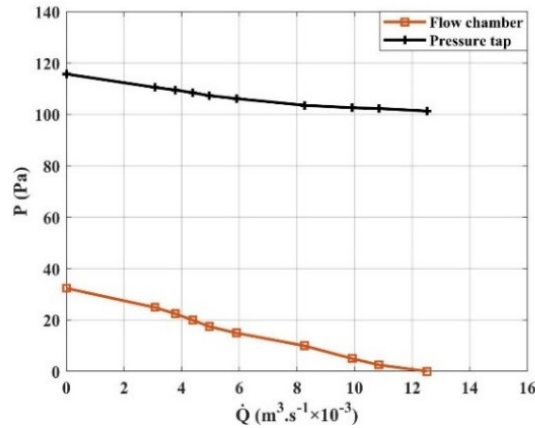
399 The comparison of the fan curves obtained using each of the three measuring techniques is illustrated in  
 400 Fig. 10. It can be inferred from this figure, that the average pressure probe readings showed good agreement  
 401 with the pressure tap readings. Both techniques provide higher pressure readings than the test chamber due  
 402 to the presence of the sub-chasses which act as blockages. Furthermore, these obstructions cause a non-  
 403 zero pressure at the free delivery point (i.e. the maximum flow delivered by the fan). Going from FE to CE,  
 404 the pressure taps results show a 1.6% drop in the flowrate supplied by the fan and 44.1% drop in the  
 405 maximum static pressure at the fan inlet This reduction of static pressure represents the enclosure’s role in  
 406 hindering flow into the fan. Hence, ITE enclosure can have a considerable effect on the fan’s static pressure.



**Fig. 10.** Fan performance curves in the CE considering various static pressure measuring techniques.

407  
 408 Lastly, the effect of blockages on fan performance was examined in SE. The results are presented in Fig.  
 409 11. The figure shows a considerable difference in the pressure readings measured by the pressure taps and  
 410 the test chamber. At the free delivery point, the flow test chamber reading shows that the static pressure

411 reading equals zero. However, the actual static pressure measurement generated by the fan was 101.3 Pa.  
 412 This discrepancy in the pressure chamber measurements is attributed to the server components around the  
 413 fan, which act as obstructions. Based on this, testing the fan inside ITE using a flow test chamber could be  
 414 misleading in terms of pressure measurements. A summary of the blockages' effect on the maximum fan  
 415 flowrate and the maximum static pressure at the fan inlet is presented in Table 6, where the maximum static  
 416 pressure represents the pressure at the fan inlet when the flow delivered by the fan equals zero.



417 **Fig. 11.** Fan performance curves based on pressure taps and test chamber static-pressure readings in SE.

**Table 6**

Operating environment effect on the fan's static pressure and flowrate.

Environment	FE	CE	SE
Pressure measuring technique	Test chamber	Pressure taps	Pressure taps
Static pressure $P$ (Pa)	$428 \pm 6.22$	$238.89 \pm 1.33$	$101.32 \pm 1.22$
Flowrate $\dot{Q}$ ( $m^3 \cdot s^{-1} \times 10^{-3}$ )	$29.26 \pm 0.15$	$28.79 \pm 0.14$	$12.51 \pm 0.06$
Total reduction in maximum pressure (Pa)	-	189.11	326.68
Total reduction in maximum flowrate ( $m^3 \cdot s^{-1} \times 10^{-3}$ )	-	0.47	16.75

418  
 419 Table 6 shows that blockages could have a significant effect on both the static pressure and the flowrate  
 420 delivered by the fan. By comparing the SE with the FE, the fan exhibited a relative reduction by 57.2% and  
 421 76.3% in terms of flowrate and static pressure, respectively. This degradation of the fan's performance will  
 422 vary according to the working environment. Moreover, various fan types and fan shapes may react  
 423 differently to blockages. Hence, it is vital to consider and investigate how a specific fan reacts to the  
 424 presence of blockages before using it in ITE. In addition, using the vendor flow curve to predict the fan  
 425 performance inside ITE may result in a large overestimation of both static pressure and flowrate.

#### 4.2. Analysis of numerical results for fan performance curve

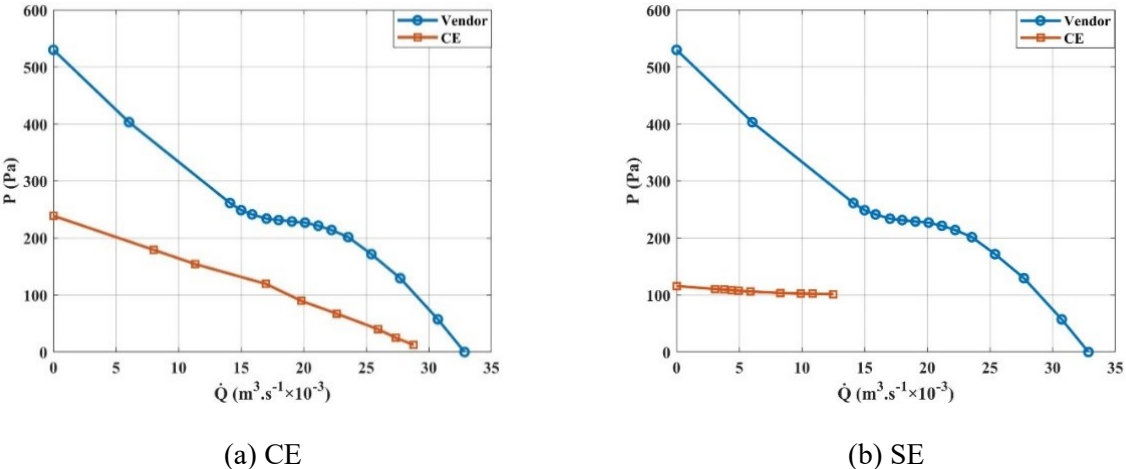
427 The LF and MRF modeling approaches were tested thoroughly in various working environments. The  
 428 experimental measurements generated from these working environments were utilized to evaluate the

429 accuracy of these modeling approaches. Table 7 compares the experimental and the CFD results considering  
 430 the maximum static pressure reading and maximum flowrate.

431 As can be noted from Table 7, both MRF and LF provide a good estimation of the fan flowrate in the FE  
 432 where the experimental maximum flowrate was measured to be  $29.26 \times 10^{-3} \text{ m}^3 \cdot \text{s}^{-1}$  and both LF and  
 433 MRF models predicted  $26.18 \times 10^{-3}$  and  $26.89 \times 10^{-3} \text{ m}^3 \cdot \text{s}^{-1}$ , respectively. For maximum static  
 434 pressure, MRF gives more accurate results than LF, with an error of 15.5% compared to 40% with reference  
 435 to experimental results, respectively. Note that LF uses the vendor curve, which was previously shown to  
 436 overestimate the fan flowrate and static pressure, to specify the pressure jump across the fan. Thus, the large  
 437 mismatch between the LF model and the experiment in the maximum static pressure values can be attributed  
 438 to this. Fig. 12 shows the vendor fan curve and the experimental flow curves in the CE and the SE.

439 In the CE, experimental results showed that the fan flowrate slightly reduced and remained 98.39% of that  
 440 of the FE while the flowrate error decreased to 2% for the LF approach, and increased to 10.8% for the  
 441 MRF approach. Moreover, it can be noted from the experimental results, that the fan experienced a steep  
 442 decrease in static pressure. This decrease was not captured by either of the modeling approaches, in fact,  
 443 the error dramatically increased from 174.19 and 70.45 (Pa) to 382.66 and 246.85 (Pa) for the LF and the  
 444 MRF models compared with the FE, respectively.

445



446 **Fig. 12.** Vendor vs experimental flow curves in the CE and SE.

447 With obstructions added in the SE, the LF approach failed to predict both static pressure and flowrate, in  
 448 comparison with the experimental results, the LF witnessed a significant deviation which was calculated to  
 449 be 508.33 (Pa) in the maximum generated static pressure and  $8.79 \times 10^{-3} \text{ m}^3 \cdot \text{s}^{-1}$  in the maximum  
 450 delivered flowrate. However, the MRF approach succeeded in predicting flowrate with an error of 3.9%  
 451 but failed to predict static pressure as it exhibited a difference of 387.99 (Pa) in the maximum generated  
 452 static pressure. Fig. 13 depicts the fan performance curves derived from the experimental and numerical  
 453 results.

454

455

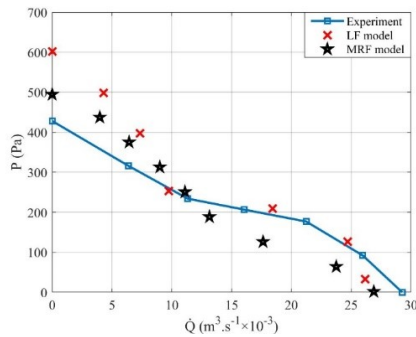
456

457

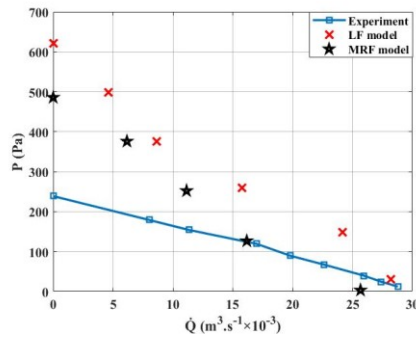
458

**Table 7**  
Experimental and CFD static pressure and flowrate readings.

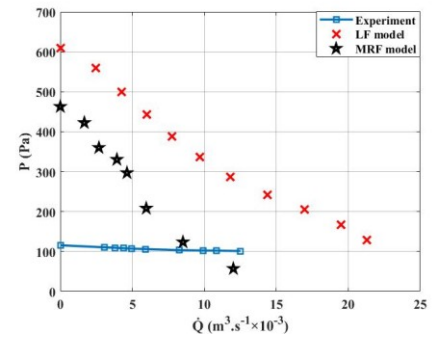
Environment	Experiment	LF	MRF
<b>FE</b>			
Static pressure $P$ (Pa)	$428 \pm 6.22$	602.19	494.45
Flowrate $\dot{Q}$ ( $m^3 \cdot s^{-1} \times 10^{-3}$ )	$29.26 \pm 0.15$	26.18	26.89
Percent error in maximum pressure (%)	-	40	15.5
Percent error in maximum flowrate (%)	-	11	8.1
<b>CE</b>			
Static pressure $P$ (Pa)	$238.89 \pm 1.33$	621.55	485.74
Flowrate $\dot{Q}$ ( $m^3 \cdot s^{-1} \times 10^{-3}$ )	$28.79 \pm 0.14$	28.22	25.67
Percent error in maximum pressure (%)	-	160	103
Percent error in maximum flowrate (%)	-	2	10.8
<b>SE</b>			
Static pressure $P$ (Pa)	$101.32 \pm 1.22$	609.65	489.31
Flowrate $\dot{Q}$ ( $m^3 \cdot s^{-1} \times 10^{-3}$ )	$12.51 \pm 0.06$	21.3	12.02
Percent error in maximum pressure (%)	-	502	388
Percent error in maximum flowrate (%)	-	70.3	3.9



(a) FE



(b) CE



(c) SE

**Fig. 13.** Experimental and numerical fan performance curves in different environments.

459

460 As can be noted from Fig. 13, in the CE and SE environments, the fan experiences a drop in the static  
 461 pressure. However, the numerical approaches estimate the static pressure in these environments without  
 462 considering this static pressure drop. In the LF model, the pressure at the fan inlet is predefined using the

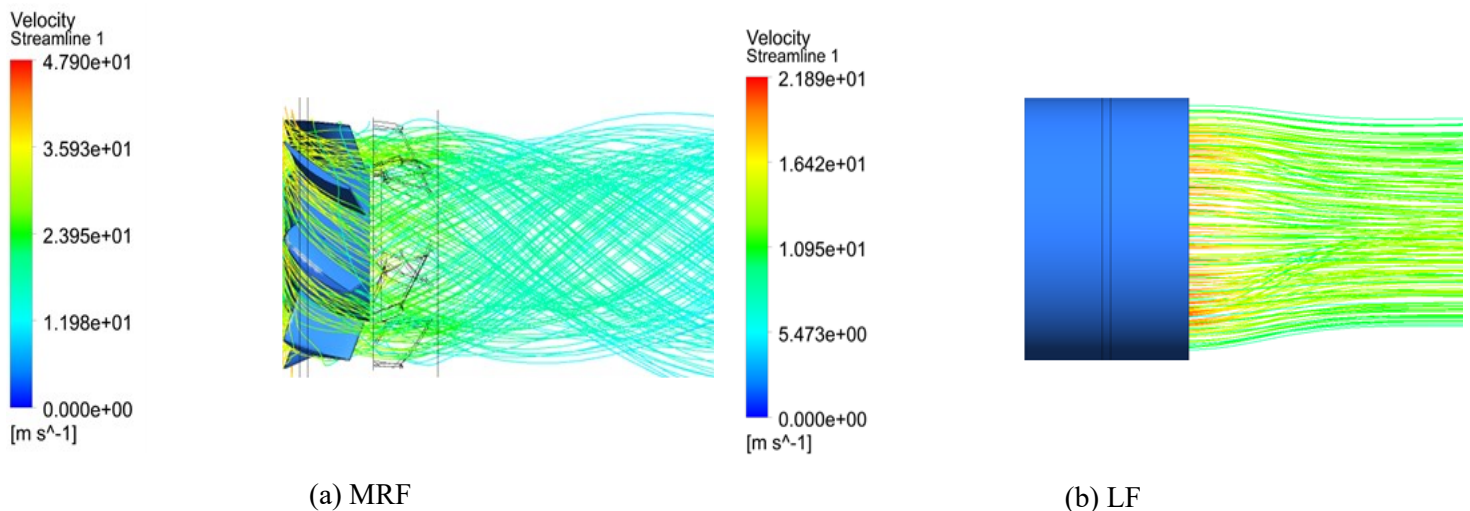
463 pressure jump equation as a boundary condition. Therefore, the fan is not experiencing a considerable drop  
464 in the generated static pressure. Based on the fact that fans that can generate a higher maximum static-  
465 pressure are more capable of overcoming the flow resistance, the flow delivered by the LF model is slightly  
466 reduced when installed in condensed environments.

467 Regarding the MRF model, the computational domain is divided into three subdomains which are the inlet  
468 and outlet stationary zones and the fan rotating zones. At the interface between these zones, the absolute  
469 velocity values in one zone are being enforced by the CFD code to satisfy the continuity equation to  
470 calculate the velocity in the adjacent zone, while the other scalar quantities, for instance, temperature,  
471 pressure, density, and turbulent kinetic energy passed without any special treatment. This might be the  
472 reason behind the error in the MRF model pressure results. Further investigation should be conducted to  
473 uncover the reason behind the reduction in the fan static pressure when installed near a blockage in future  
474 studies. Also, this should be used to find the exact reason behind the mismatch between the MRF model  
475 results and the experimental results.

### 476 4.3. Analysis of fan flow field

477 Besides the fan flowrate and static pressure, the flow field created by the fan play a vital role in evaluating  
478 the fan's cooling performance. Given that fans with different flow fields will cause different temperature  
479 distributions, it is essential to study the flow field within the ITE. In the case of this study, it was done using  
480 MRF and LF. Since, MRF utilizes the actual fan body to define the flow field, while LF assumes a uniform  
481 flow field distribution, they are predicting different flow patterns. The fan flow field generated by each  
482 approach is illustrated in Fig. 14.

483

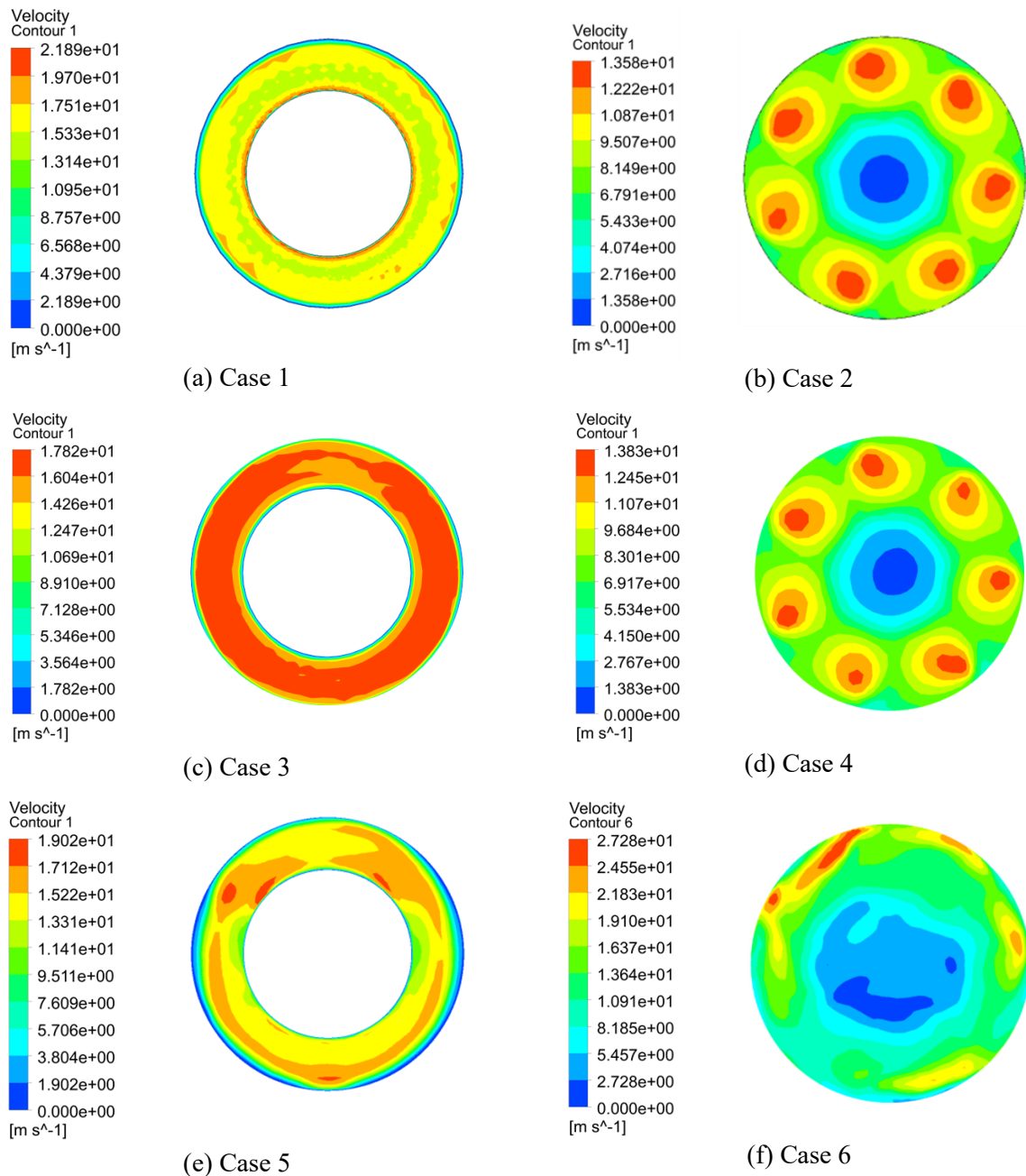


484 **Fig. 14.** Fan flow field generated by MRF and LF approaches.

485

486 The flow field created by the two modeling approaches was investigated in the three environments. Fig. 15  
487 displays the velocity contours for cases 1–6 at the fan inlet. This figure demonstrates that the MRF and LF  
488 velocity contours at the fan inlet are completely different, which indicates that upstream of the fan the flow  
489 distribution must also be dissimilar. As a result, this will be reflected in temperature distribution inside the  
490 ITE. Moreover, Fig. 15 shows that the LF and MRF approaches react to the presence of obstructions in  
491 different ways. The velocity contours for cases 5 and 6 show how the velocity distribution changes when

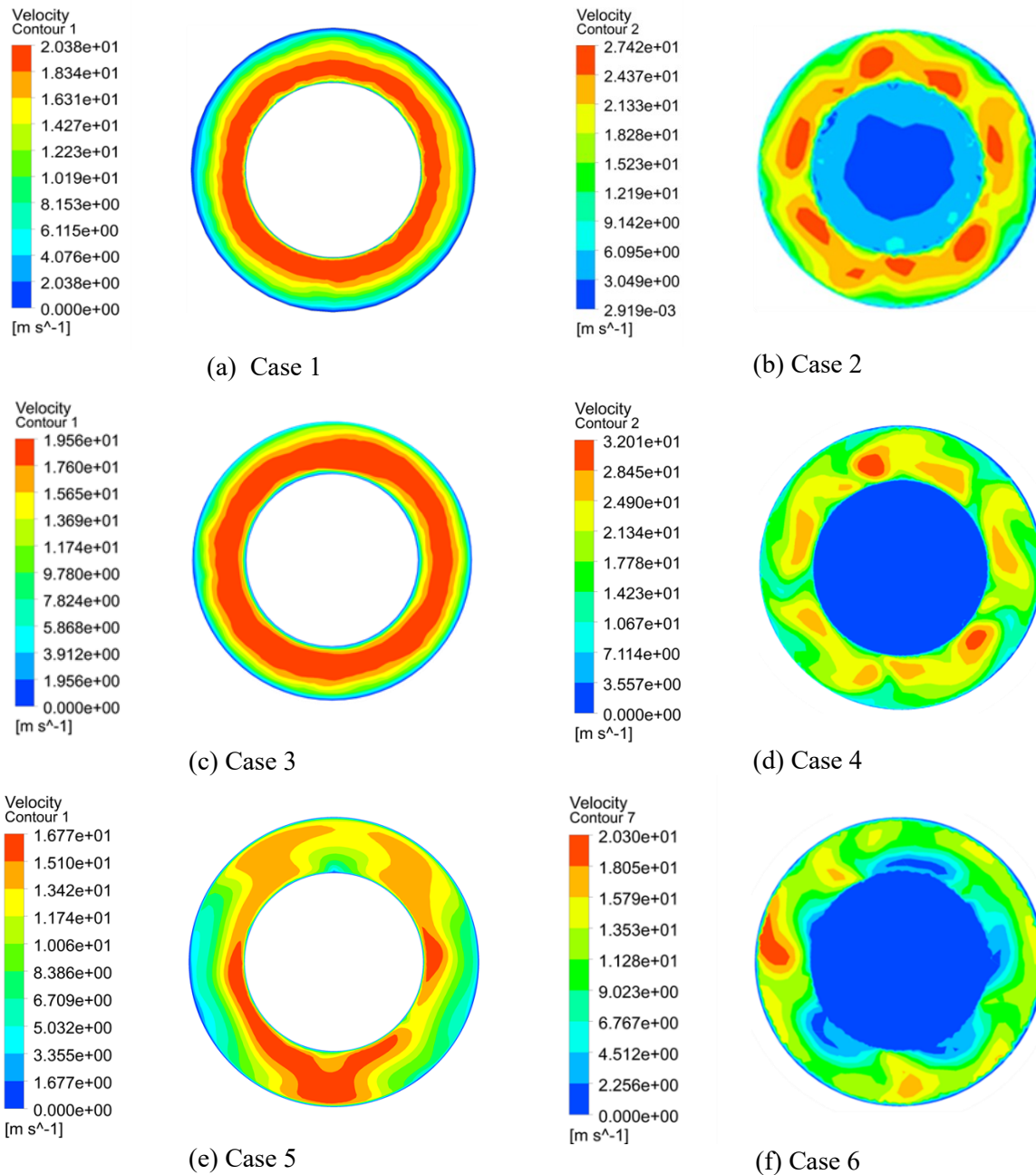
491 the server components are installed. By comparing the velocity contours for these cases, it can be inferred  
 492 that the flow field of the MRF is more sensitive to blockages At the fan inlet for case 6 (MRF), the flow  
 493 shows a higher velocity in the upper half of the fan, whereas for case 5 (LF) it shows near equal velocities  
 494 in the upper and lower halves of the fan.



**Fig. 15.** Velocity contours at the fan inlet.

495  
 496 Further investigation was carried out for the velocity distribution at the fan outlet. Fig. 16 shows the velocity  
 497 contours for cases 1–6 at the fan outlet. Much like with the velocity inlet contours, the MRF and LF models  
 498 generate different velocity distributions at the fan outlet in each environment. In the MRF models, the fan

499 outlet guide vanes were considered. By comparing the inlet velocity contours with outlet ones, it clear that  
 500 the flow is more uniformly distributed at the fan inlet.



**Fig. 16.** Velocity contours at the fan outlet

501

502 In the LF model, the flow field is uniform at the fan inlet when no obstructions are installed as the inlet  
 503 surface is assumed to have a constant pressure jump along the surface. However, due to the friction forces  
 504 between the flow and fan walls, the flow profile reshapes to have a higher velocity in the middle. On the  
 505 other hand, the MRF tends to have a higher velocity between the fan blades at the fan inlet, this is attributed  
 506 to the fact the rotating frame is not actually rotating, instead a constant rotational speed is assigned to this  
 507 frame. At the fan outlet, the flow reshapes due to the interaction with the fan's outlet guide vanes.



#### 508 4.4. Analysis of the flow field inside the heat sink

509 Finally, to better understand how the LF and MRF approaches affect the heat transfer prediction within the  
510 ITE (cases 5 and 6), the velocity field in the heat sink was explored. The heat sink lies  $16\text{ m} \times 10^{-3}$  away  
511 from the fan outlet, as shown in Fig. 4 (e). In the LF model, the flowrate through the heat sink was calculated  
512 as  $11.87\text{ m}^3 \cdot \text{s}^{-1} \times 10^{-3}$ . For the MRF model, the flowrate was equal to  $7.07\text{ m}^3 \cdot \text{s}^{-1} \times 10^{-3}$ .  
513 Furthermore, the Reynolds number (Re) calculated for the LF and MRF models were found to be 385 and  
514 228.9, respectively. Hence, the overall heat transferred from the heat sink is overpredicted in the LF model  
515 due to the higher flowrate considered and the elevated heat transfer coefficient. Fig. 17 shows the velocity  
516 contours at the corresponding heat sink.

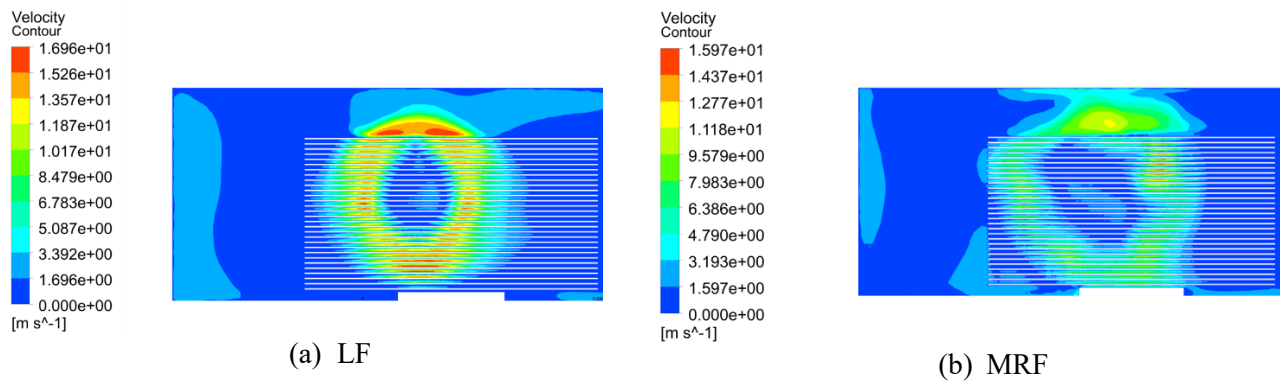


Fig. 17. Velocity contours at the inlet of the heat sink at the fan outlet.

517

#### 518 5. Conclusions

519 Based on these experimental results, it can be concluded that the fans encounter a steep reduction in static  
520 pressure when they are installed in the ITE enclosure. When the ITE equipment components are considered,  
521 a huge degradation in the overall fan performance is noted. The fan flowrate and the static pressure decrease  
522 by 57.2% and 76.3%, respectively. This effect of blockage on the fan performance cannot be inferred from  
523 the fan performance curve. Hence, it is extremely important to consider and investigate how the fan reacts  
524 to the presence of blockages before using it in ITE. Moreover, when testing a fan inside ITE, it is necessary  
525 to consider local pressure measurement rather than the flow test chamber to report the static pressure  
526 readings.

527 Comparing the numerical LF and MRF approaches with the experimental results show that both models  
528 can predict the fan performance in the FE. Inside ITE, the LF approach overestimates the flowrate delivered  
529 by the test fan by an additional  $8.79\text{ m}^3 \cdot \text{s}^{-1} \times 10^{-3}$ . Moreover, the LF model static pressure is not affected  
530 by the presence of obstructions, contrasting the experimental results. The MRF model flowrate shows a  
531 good agreement with the experimental results in the three different environments with a maximum error of  
532 10.8%. However, this approach failed to predict the fan's static pressure.

533 Consequently, the LF model's overestimation of flowrate results in an overvaluation of the Re and flowrate  
534 through the heat sink at the back of the fan. The flowrate and Re calculated using the LF model are 67.9%  
535 and 68.2%, respectively, which are higher than those calculated using the MRF approach.

536 Ultimately, the LF approach is deemed suitable for applications with no obstructions around the fan, but it  
537 is not recommended for predicting the flow field or heat transfer in highly restrictive environments. Instead,  
538 using the MRF approach in these environments could significantly decrease the error. Furthermore, when

539 MRF is employed in such environments no conclusions should be carried out regarding the static pressure  
540 readings.

#### 541 **Acknowledgments**

542 We would like to acknowledge, Future Facilities Ltd and ES2 Partner Universities for their support and  
543 advice. Also, authors would like to acknowledge the reviewers for their constructive comments. This work  
544 is supported by NSF IUCRC Award No. IIP- 1738793 and MRI Award No. CNS1040666.

#### 545 **References**

- 546 [1] V. Choudhari, A. Dhoble, S. Panchal, Numerical analysis of different fin structures in phase change  
547 material module for battery thermal management system and its optimization, *International Journal of*  
548 *Heat and Mass Transfer*, 163 (2020) 120434.
- 549 [2] Y. Lai, W. Wu, K. Chen, S. Wang, C. Xin, A compact and lightweight liquid-cooled thermal  
550 management solution for cylindrical lithium-ion power battery pack, *International Journal of Heat and*  
551 *Mass Transfer*, 144 (2019) 118581.
- 552 [3] D. Kong, R. Peng, P. Ping, J. Du, G. Chen, J. Wen, A novel battery thermal management system  
553 coupling with PCM and optimized controllable liquid cooling for different ambient temperatures, *Energy*  
554 *Conversion and Management*, 204 (2020) 112280.
- 555 [4] L. Zhao, Z. Zheng, B. Guo, Z. Yang, Experimental investigation on the thermal performance of air-  
556 cooled multi-port flat heat pipes, *International Journal of Heat and Mass Transfer*, 154 (2020) 119600.
- 557 [5] M. Bahiraei, S. Heshmatian, Electronics cooling with nanofluids: a critical review, *Energy Conversion*  
558 *and Management*, 172 (2018) 438-456.
- 559 [6] Y.M. Manaserh, M.I. Tradat, G. Mohsenian, B.G. Sammakia, M.J. Seymour, General Guidelines for  
560 Commercialization a Small-Scale In-Row Cooled Data Center: A Case Study, in: 2020 36th  
561 Semiconductor Thermal Measurement, Modeling & Management Symposium (SEMI-THERM), IEEE,  
562 2020, pp. 48-55.
- 563 [7] C. Caceres, A. Ortega, A. Wemhoff, G.F. Jones, Numerical Analysis of Two Phase Cross-Flow Heat  
564 Exchanger for High Power Density Equipment in Data Centers under Dynamic Conditions, in: 2020 19th  
565 IEEE Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems  
566 (ITherm), IEEE, 2020, pp. 520-529.
- 567 [8] C.H. Hoang, M. Tradat, Y. Manaserh, B. Ramakrisnan, S. Rangarajan, Y. Hadad, S. Schiffres, B.  
568 Sammakia, Liquid Cooling Utilizing a Hybrid Microchannel/Multi-Jet Heat Sink: A Component Level  
569 Study of Commercial Product, in: ASME 2020 International Technical Conference and Exhibition on  
570 Packaging and Integration of Electronic and Photonic Microsystems, American Society of Mechanical  
571 Engineers Digital Collection, 2020.
- 572 [9] M. Tradat, G. Mohsenian, Y. Manaserh, B. Sammakia, D. Mendo, H.A. Alissa, Experimental Analysis  
573 of Different Measurement Techniques of Server-Rack Airflow Predictions Towards Proper DC Airflow  
574 Management, in: 2020 19th IEEE Intersociety Conference on Thermal and Thermomechanical  
575 Phenomena in Electronic Systems (ITherm), IEEE, 2020, pp. 366-373.
- 576 [10] Mohammad I. Tradat, Yaman M. Manaserh, Bahgat G. Sammakia, Cong Hiep Hoang, Husam A.  
577 Alissa, An Experimental and Numerical Investigation of Novel Solution for Energy Management  
578 Enhancement in Data Centers Using Underfloor Plenum Porous Obstructions. *Applied Energy*, In press  
579 (Accepted) (2021).
- 580 [11] A. Taheri, M.G. Moghadam, M. Mohammadi, M. Passandideh-Fard, M. Sardarabadi, A new design  
581 of liquid-cooled heat sink by altering the heat sink heat pipe application: Experimental approach and  
582 prediction via artificial neural network, *Energy Conversion and Management*, 206 (2020) 112485.
- 583 [12] B. Kanargi, P.S. Lee, C. Yap, A numerical and experimental investigation of heat transfer and fluid  
584 flow characteristics of an air-cooled oblique-finned heat sink, *International Journal of Heat and Mass*  
585 *Transfer*, 116 (2018) 393-416.

586 [13] H.H. Saber, S.A. AlShehri, W. Maref, Performance optimization of cascaded and non-cascaded  
587 thermoelectric devices for cooling computer chips, *Energy Conversion and Management*, 191 (2019) 174-  
588 192.

589 [14] T. Yeom, L. Huang, M. Zhang, T. Simon, T. Cui, Heat transfer enhancement of air-cooled heat sink  
590 channel using a piezoelectric synthetic jet array, *International Journal of Heat and Mass Transfer*, 143  
591 (2019) 118484.

592 [15] M. Yang, M.-T. Li, Y.-C. Hua, W. Wang, B.-Y. Cao, Experimental study on single-phase hybrid  
593 microchannel cooling using HFE-7100 for liquid-cooled chips, *International Journal of Heat and Mass  
594 Transfer*, 160 (2020) 120230.

595 [16] J. Stafford, E. Walsh, V. Egan, R. Grimes, Flat plate heat transfer with impinging axial fan flows,  
596 *International Journal of Heat and Mass Transfer*, 53(25-26) (2010) 5629-5638.

597 [17] J. Stafford, E. Walsh, V. Egan, Local heat transfer performance and exit flow characteristics of a  
598 miniature axial fan, *International journal of heat and fluid flow*, 31(5) (2010) 952-960.

599 [18] D. Jang, K.-S. Lee, Flow characteristics of dual piezoelectric cooling jets for cooling applications in  
600 ultra-slim electronics, *International Journal of Heat and Mass Transfer*, 79 (2014) 201-211.

601 [19] W.L. Staats, J. Brisson, Active heat transfer enhancement in air cooled heat sinks using integrated  
602 centrifugal fans, *International Journal of Heat and Mass Transfer*, 82 (2015) 189-205.

603 [20] J. Stafford, E. Walsh, V. Egan, The effect of global cross flows on the flow field and local heat  
604 transfer performance of miniature centrifugal fans, *International journal of heat and mass transfer*, 55(7-8)  
605 (2012) 1970-1985.

606 [21] S.-C. Lin, C.-A. Chou, Blockage effect of axial-flow fans applied on heat sink assembly, *Applied  
607 thermal engineering*, 24(16) (2004) 2375-2389.

608 [22] S.-C. Lin, F.-S. Chuang, C.-A. Chou, C.-W. Sun, Z.-H. Yang, Blockage Effect of the Centrifugal  
609 Cooling Fans, in: *Thermal Sciences 2004. Proceedings of the ASME-ZSIS International Thermal Science  
610 Seminar II*, Begel House Inc., 2004.

611 [23] S. Nakamura, M. Takahashi, K. Sato, K. Yokota, Influence of an Upstream Obstacle on the Flow  
612 Characteristics of Axial-flow Fans, in: *Fluids Engineering Division Summer Meeting, American Society  
613 of Mechanical Engineers*, 2014, pp. V01BT10A017.

614 [24] K. Ochiai, S. Nakamura, K. Sato, D. Kang, K. Yokota, Flow Characteristics of Axial-Flow Fans  
615 With an Upstream/Downstream Blockage Disk, in: *Fluids Engineering Division Summer Meeting,  
616 American Society of Mechanical Engineers*, 2017, pp. V01AT03A011.

617 [25] A. Al-Salaymeh, O. Badran, The Influence of Inlet and Outlet Grilles on the Flow Characteristics of  
618 Axial Fans.

619 [26] T. Fukue, M. Ishizuka, T. Hatakeyama, S. Nakagawa, K. Koizumi, Study on PQ curves of cooling  
620 fans for thermal design of electronic equipment (Effects of opening position of obstructions near a fan),  
621 in: *Fluids Engineering Division Summer Meeting*, 2011, pp. 737-745.

622 [27] T. Fukue, T. Hatakeyama, M. Ishizuka, K. Hirose, K. Koizumi, Relationships between supply flow  
623 rate of small cooling fans and pressure drop characteristics in electronic enclosure, in: *International  
624 Electronic Packaging Technical Conference and Exhibition, American Society of Mechanical Engineers*,  
625 2013, pp. V002T008A020.

626 [28] T. Fukue, K. Hirose, T. Hatakeyama, M. Ishizuka, K. Koizumi, Evaluation of pressure drop  
627 characteristics around axial cooling fans with electrical components, in: *2016 International Conference  
628 on Electronics Packaging (ICEP), IEEE*, 2016, pp. 173-178.

629 [29] G.V. Shankaran, M.B. Dogruoz, Validation of an advanced fan model with multiple reference frame  
630 approach, in: *2010 12th IEEE intersociety conference on thermal and thermomechanical phenomena in  
631 electronic systems, IEEE*, 2010, pp. 1-9.

632 [30] R. Boukhanouf, A. Haddad, A CFD analysis of an electronics cooling enclosure for application in  
633 telecommunication systems, *Applied Thermal Engineering*, 30(16) (2010) 2426-2434.

634 [31] P.S. Nasirabadi, S.M. Ghiaasiaan, J.H. Hattel, Long term prediction of local climate inside an  
635 electronics enclosure, *International Journal of Heat and Mass Transfer*, 137 (2019) 280-291.

636 [32] Z. Song, Studying the fan-assisted cooling using the Taguchi approach in open and closed data  
637 centers, *International Journal of Heat and Mass Transfer*, 111 (2017) 593-601.

638 [33] H.A. Alissa, K. Nemati, U.L. Puvvadi, B.G. Sammakia, K. Schneebeli, M. Seymour, T. Gregory,  
639 Analysis of airflow imbalances in an open compute high density storage data center, *Applied Thermal*  
640 *Engineering*, 108 (2016) 937-950.

641 [34] M.B. Dogruoz, G. Shankaran, Computations with the multiple reference frame technique: Flow and  
642 temperature fields downstream of an axial fan, *Numerical Heat Transfer, Part A: Applications*, 71(5)  
643 (2017) 488-510.

644 [35] J. Luo, A. Gosman, Prediction of impeller-induced flow in mixing vessels using multiple frames of  
645 reference, in, *INSTITUTE OF CHEMICAL ENGINEERS SYMPOSIUM SERIES*, 1994.

646 [36] Y.T.a.L. Lee, H.C., 2016. Performance assessment of various fan ribs inside a centrifugal blower.  
647 *Energy*, 94, pp.609-622.

648 [37] X. Ye, Zhang, J. and Li, C., 2017. Effect of blade tip pattern on performance of a twin-stage  
649 variable-pitch axial fan. *Energy*, 126, pp.535-563.

650 [38] L. Zhang, He, R., Wang, X., Zhang, Q. and Wang, S., 2019. Study on static and dynamic  
651 characteristics of an axial fan with abnormal blade under rotating stall conditions. *Energy*, 170, pp.305-  
652 325.

653 [39] B. Jiang, Wang, J., Yang, X., Wang, W. and Ding, Y., 2019. Tonal noise reduction by unevenly  
654 spaced blades in a forward-curved-blades centrifugal fan. *Applied Acoustics*, 146, pp.172-183.

655 [40] G. Shankaran, M.B. Dogruoz, Advances in fan modeling: Using multiple reference frame (mrf)  
656 approach on blowers, in: *International Electronic Packaging Technical Conference and Exhibition*, 2011,  
657 pp. 259-267.

658 [41] M.B. Dogruoz, G. Shankaran, Advances in fan modeling: issues and effects on thermal design of  
659 electronics, in: *ASME International Mechanical Engineering Congress and Exposition*, American Society  
660 of Mechanical Engineers, 2012, pp. 1515-1522.

661 [42] C. Zhou, C. Yang, C. Wang, X. Zhang, Numerical simulation on a thermal management system for a  
662 small data center, *International Journal of Heat and Mass Transfer*, 124 (2018) 677-692.

663 [43] A.A.S.-A.S. 51-16, Laboratory Methods of Testing Fans for Certified Aerodynamic Performance  
664 Rating, in, *Air Movement and Control Association International Inc.*, 2016.

665 [44] K.A. Banaszynski, Design and qualification of an experimental facility for performing fluid  
666 mechanics and heat transfer measurements in a turbulent channel flow over a two-dimensional obstacle,  
667 (1992).

668 [45] A.A.S.-A.A. 51-1999), Laboratory method of testing fans for aerodynamic performance rating, in,  
669 *Air Movement and Control Association, Inc.*, 1999.

670 [46] R.W. Whitesides, Basic Pump Parameters and the Affinity Laws, PDH Center, Fairfax, VA, (2012).

671 [47] R. Franzke, CFD modelling of axial fans for thermal management applications, *Chalmers Tekniska*  
672 *Hogskola (Sweden)*, 2019.

673 [48] P. Gullberg, L. Löfdahl, S. Adelman, P. Nilsson, An Investigation and correction method of  
674 stationary fan CFD MRF simulations, 0148-7191, *SAE Technical Paper*, 2009.

675 [49] A. Kasaeian, A.R. Mahmoudi, F.R. Astarai, A. Hejab, 3D simulation of solar chimney power plant  
676 considering turbine blades, *Energy Conversion and Management*, 147 (2017) 55-65.

677 [50] Y.-J. Jung, H. Jeon, Y. Jung, K.-J. Lee, M. Choi, Effects of recessed blade tips on stall margin in a  
678 transonic axial compressor, *Aerospace Science and Technology*, 54 (2016) 41-48.

679 [51] F. Kameier, W. Neise, Experimental study of tip clearance losses and noise in axial turbomachines  
680 and their reduction, (1997).

681 [52] R. Achouri, I. Mokni, H. Mhiri, P. Bournot, A 3D CFD simulation of a self inducing Pitched Blade  
682 Turbine Downflow, *Energy conversion and management*, 64 (2012) 633-641.

683 [53] H. Zhao, C. Kang, K. Ding, Y. Zhang, B. Li, Transient startup characteristics of a drag-type  
684 hydrokinetic turbine rotor, *Energy Conversion and Management*, 223 (2020) 113287.

- 685 [54] Z. Xu, Y.-H. Feng, C.-Y. Zhao, Y.-L. Huo, S. Li, X.-J. Hu, Y.-J. Zhong, Experimental and numerical  
686 investigation on aerodynamic performance of a novel disc-shaped wind rotor for the small-scale wind  
687 turbine, *Energy Conversion and Management*, 175 (2018) 173-191.
- 688 [55] M. Mohamed, Performance investigation of H-rotor Darrieus turbine with new airfoil shapes,  
689 *Energy*, 47(1) (2012) 522-530.
- 690 [56] A.T. Shirazi, M.R. Nazari, M.D. Manshadi, Numerical and experimental investigation of the fluid  
691 flow on a full-scale pump jet thruster, *Ocean Engineering*, 182 (2019) 527-539.
- 692 [57] P. Huang, P. Bradshaw, T. Coakley, Skin friction and velocity profile family for compressible  
693 turbulent boundary layers, *AIAA journal*, 31(9) (1993) 1600-1604.
- 694 [58] M. Peric, S. Ferguson, The advantage of polyhedral meshes, *Dynamics*, 24 (2005) 45.
- 695 [59] M. Spiegel, T. Redel, Y.J. Zhang, T. Struffert, J. Hornegger, R.G. Grossman, A. Doerfler, C.  
696 Karmonik, Tetrahedral vs. polyhedral mesh size evaluation on flow velocity and wall shear stress for  
697 cerebral hemodynamic simulation, *Computer methods in biomechanics and biomedical engineering*,  
698 14(01) (2011) 9-22.
- 699 [60] E. Tannoury, S. Khelladi, B. Demory, M. Henner, F. Bakir, Influence of blade compactness and  
700 segmentation strategy on tonal noise prediction of an automotive engine cooling fan, *Applied acoustics*,  
701 74(5) (2013) 782-787.
- 702 [61] M. Darvish, S. Frank, Numerical Investigations on the Performance Characteristic of Radial Fans  
703 with forward curved blades by means of CFD, Master Thesis, HTW Berlin, 2010.
- 704 [62] O. Singh, R. Khilwani, T. Sreenivasulu, M. Kannan, Parametric study of centrifugal fan  
705 performance: experiments and numerical simulation, *International Journal of Advances in Engineering &*  
706 *Technology*, 1(2) (2011) 33-50.
- 707 [63] X. Ye, X. Ding, J. Zhang, C. Li, Numerical simulation of pressure pulsation and transient flow field  
708 in an axial flow fan, *Energy*, 129 (2017) 185-200.
- 709 [64] M. Stevens, Fan performance, Air Movement and Control Association International, (2016).
- 710 [65] L. Twin City Fan Companies, Fan Engineering: Temperature & Altitude Effects On Fans, 2018.

711